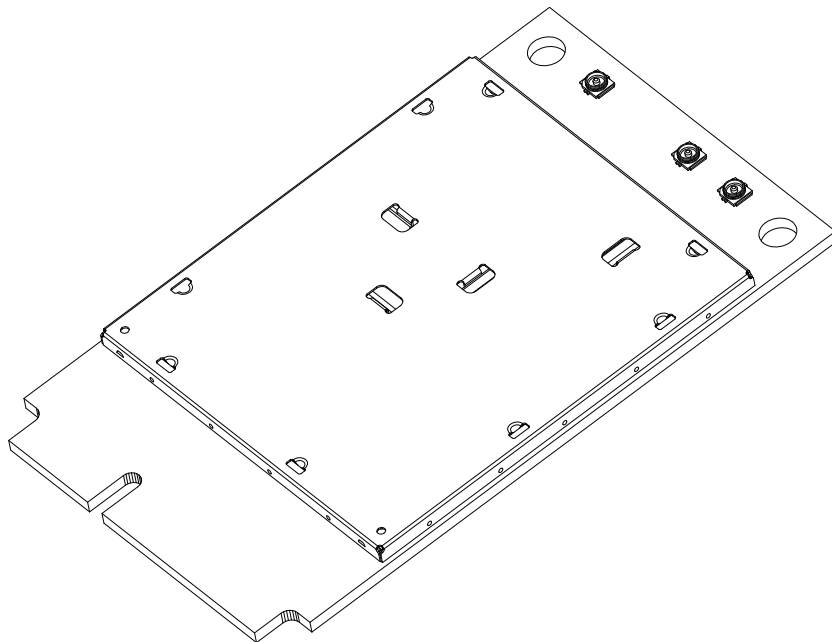




Product Technical Specification & Customer Design Guidelines

AirPrime MC7455



SIERRA
WIRELESS®

4116238

Rev 9

Proprietary and Confidential
Contents subject to change

Important Notice

Due to the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless accepts no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

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|---|--|
| Sales information and technical support, including warranty and returns | Web: sierrawireless.com/company/contact-us/ Global toll-free number: 1-877-687-7795 6:00 am to 6:00 pm PST |
| Corporate and product information | Web: sierrawireless.com |

Revision History

| Revision number | Release date | Changes |
|-----------------|----------------|---|
| 1 | October 2014 | Initial release. |
| 2 | October 2014 | Updated system block (Figure 3-1), LTE Rx sensitivity (Table 4-4), UMTS Rx sensitivity (Table 4-5), Tx tolerances (Table 4-6) |
| 3 | February 2015 | Updated Table 4-4 on page 44 (LTE sensitivity) Updated Table 4-5 on page 45 (UMTS sensitivity) Updated Table 4-6 on page 45 (Tx power) Updated typo in table 3-4 (USIM2_GND) Updated Table 4-7 on page 45 (# of satellites) Updated description/functionality of W_DISABLE_N |
| 4 | September 2015 | Updated Carrier Aggregation combinations (Table 1-2 on page 16) Corrected SIM signal descriptions/notes (Table 3-4 on page 31) Added LTE B30 Removed LTE B17 Removed LTE CA B30+B29 Updated Table 4-4 on page 44 (LTE sensitivity) Updated Table 4-5 on page 45 (UMTS sensitivity) Updated Table 4-6 on page 45 (Tx power) |

| Revision number | Release date | Changes |
|-----------------|---------------|---|
| 5 | November 2015 | <p>Updated Figure 3-2 on page 25 (RF block diagram)</p> <p>Updated system reset time (SYSTEM_RESET_N—Reset Input on page 36)</p> <p>Updated module weight (Table 7-1 on page 57)</p> <p>Added signal strength for acquisition time values (Table 4-7 on page 45)</p> <p>Updated power-on/off timing values</p> <p>Updated minimum Vcc value to 3.135V</p> <p>Updated USB signal voltages (Table 3-1 on page 26)</p> <p>Minor update to wording for heat sink location in Thermal Considerations on page 60</p> |
| 6 | January 2016 | <p>Updated temperature description/details to reflect device performance, including:</p> <ul style="list-style-type: none"> • Physical Features on page 16—Clarified temperature range as 'ambient'. • Physical Features on page 16 and Module Integration Testing on page 61—Added AT!PCTEMP to note and adjusted suggested 'best performance' max temperature. • Table 5-5 on page 50—Added explanatory note for TEMP_HI_WARN state. • Table 7-1 on page 57—Clarified temperature ranges as 'ambient'. <p>Adjusted GNSS tracking sensitivity specification to -160 dBm from -161 dBm to reflect tolerance range of measurement (Table 4-7 on page 45).</p> |
| 7 | April 2016 | <p>Updated W_DISABLE pin description, footnote, and voltage values in Table 3-1 on page 26 and in W_DISABLE_N — Wireless Disable on page 35.</p> <p>Added notes indicating signals should not be driven until device is powered on, in Host Interface Pin Assignments on page 25 and Power-On/Off Timing on page 51.</p> <p>Modified note indicating USB2.0 and 3.0 support in USB Interface on page 30.</p> <p>Added Figure 7-5, Copper Pad Location on Bottom Side of Module, on page 61.</p> <p>Added LTE bandwidth support (Table 4-2 on page 42) and LTE CA bandwidth support (Table 4-3 on page 43, Table 4-4 on page 44, Table 4-5 on page 44)</p> <p>Updated pulse width in SYSTEM_RESET_N—Reset Input on page 36</p> <p>Removed Japan (MIC) from Regulatory certifications list.</p> |
| 8 | May 2016 | <p>Corrected ripple voltage value in Power Supply Noise on page 52</p> <p>Added 'Important' notes regarding Band 30 Tx output power, and Band 30 restriction for external vehicle antennas, in Important Compliance Information for North American Users on page 64</p> <p>Updated most values in Table 5-1 on page 47 and Table 5-2 on page 48</p> |
| 9 | August 2016 | <p>Removed gpsOneXTRA.</p> <p>Noted Sprint ISIM card requirement (SIM Interface on page 31).</p> <p>Added USB3.0 signal to Signal Timing figure (Figure 5-2 on page 51); added USB3.0 timing table (Table 5-8 on page 52).</p> <p>Updated USB2.0 timing (Table 5-6 on page 51, Table 5-7 on page 52).</p> <p>Updated Band 30 regulatory note (page 65).</p> |

»» Contents

| | |
|--|-----------|
| Introduction | 15 |
| Supported RF Bands | 15 |
| Physical Features | 16 |
| Application Interface Features | 16 |
| Modem Features | 17 |
| LTE Features | 17 |
| Short Message Service (SMS) Features | 18 |
| Position Location (GNSS) | 18 |
| Supporting Documents | 18 |
| Accessories | 19 |
| Required Connectors | 19 |
| Ordering Information | 19 |
| Integration Requirements | 19 |
| | |
| Standards Compliance | 21 |
| | |
| Electrical Specifications | 23 |
| Host Interface Pin Assignments | 25 |
| Power Supply | 30 |
| USB Interface | 30 |
| USB Throughput Performance | 31 |
| User-developed Drivers | 31 |
| SIM Interface | 31 |
| SIM Implementation | 33 |
| Control Interface (Signals) | 34 |
| WAKE_N — Wake Host | 34 |
| W_DISABLE_N — Wireless Disable | 35 |
| WAN_LED_N—LED Output | 35 |
| SYSTEM_RESET_N—Reset Input | 36 |

- Antenna Control 36
- RF Specifications 37**
 - RF Connections 37
 - Shielding 37
 - Antenna and Cabling 38
 - Ground Connection 39
 - Interference and Sensitivity 39
 - Interference From Other Wireless Devices 39
 - Host-generated RF Interference 39
 - Device-generated RF Interference 40
 - Methods to Mitigate Decreased Rx Performance 40
 - Radiated Spurious Emissions (RSE) 40
 - Radiated Sensitivity Measurement 40
 - Sierra Wireless' Sensitivity Testing and Desensitization Investigation . . 41
 - Sensitivity vs. Frequency 41
 - Supported Frequencies 41
 - Conducted Rx Sensitivity / Tx Power 44
 - GNSS Specifications 45
- Power 47**
 - Power Consumption 47
 - Module Power States 49
 - Power State Transitions 50
 - Power Interface 51
 - Power Ramp-up 51
 - Power-On/Off Timing 51
 - Power Supply Noise 52
 - SED (Smart Error Detection) 52
 - Tx Power Control 53
- Software Interface 55**
 - Support Tools 55

| | |
|---|-----------|
| USB Interface | 55 |
| Mechanical and Environmental Specifications | 57 |
| Device Views | 58 |
| Labeling | 59 |
| Electrostatic Discharge (ESD) | 59 |
| Thermal Considerations | 60 |
| Regulatory Compliance and Industry Certifications | 63 |
| Important Notice | 63 |
| Safety and Hazards | 64 |
| Important Compliance Information for North American Users | 64 |
| Audio Support | 67 |
| PCM/I2S Audio Interface | 68 |
| Antenna Specification | 71 |
| Recommended Main/Diversity Antenna Specifications | 71 |
| Recommended GNSS Antenna Specifications | 73 |
| Antenna Tests | 74 |
| Design Checklist | 75 |
| Testing | 77 |
| AT Command Entry Timing Requirement | 77 |
| Acceptance Testing | 77 |
| Acceptance Test Requirements | 78 |
| Acceptance Test Procedure | 78 |
| Certification Testing | 78 |
| Production Testing | 79 |

| | |
|--|------------|
| Functional Production Test | 79 |
| Production Test Procedure | 80 |
| UMTS (WCDMA) RF Transmission Path Test | 82 |
| UMTS (WCDMA) RF Receive Path Test | 84 |
| LTE RF Receive Path Test | 86 |
| GNSS RF Receive Path Test | 88 |
| Quality Assurance Testing. | 88 |
| Suggested Testing Equipment. | 89 |
| Testing Assistance Provided by Sierra Wireless | 89 |
| IOT/Operator Testing. | 89 |
| Extended AT Commands for Testing. | 90 |
| Packaging | 93 |
| References | 95 |
| Sierra Wireless Documents | 95 |
| Command Documents | 95 |
| Other Sierra Documents | 95 |
| Industry/Other Documents | 95 |
| LTE CA Bandwidth Support | 97 |
| Acronyms | 101 |
| Index. | 107 |

List of Tables

| | |
|--|----|
| Table 1-1: Supported RF Bands | 15 |
| Table 1-2: Carrier Aggregation Combinations | 16 |
| Table 1-3: Required Host-Module Connectors | 19 |
| Table 2-1: Standards Compliance | 21 |
| Table 3-1: Connector Pin Assignments | 26 |
| Table 3-2: Power and Ground Specifications | 30 |
| Table 3-3: USB Interfaces | 30 |
| Table 3-4: SIM Interface Signals | 31 |
| Table 3-5: Module Control Signals | 34 |
| Table 3-6: W_DISABLE_N Usage | 35 |
| Table 3-7: Antenna Control Signals | 36 |
| Table 4-1: LTE Frequency Bands | 42 |
| Table 4-2: LTE Bandwidth support | 42 |
| Table 4-3: WCDMA Frequency Bands | 43 |
| Table 4-4: Conducted Rx (Receive) Sensitivity—LTE Bands | 44 |
| Table 4-5: Conducted Rx (Receive) Sensitivity—UMTS Bands | 45 |
| Table 4-6: Conducted Tx (Transmit) Power Tolerances | 45 |
| Table 4-7: GNSS Specifications | 45 |
| Table 5-1: Averaged Standby DC Power Consumption | 47 |
| Table 5-2: Averaged Call Mode DC Power Consumption | 48 |
| Table 5-3: Miscellaneous DC Power Consumption | 48 |
| Table 5-4: Module Power States | 49 |
| Table 5-5: Power State Transition Trigger Levels | 50 |
| Table 5-6: USB 2.0 Power-On/Off Timing Parameters (Double Enumeration) | 51 |
| Table 5-7: USB 2.0 Power-On/Off Timing Parameters (Single Enumeration) | 52 |
| Table 5-8: USB 3.0 Power-On/Off Timing Parameters (Single Enumeration) | 52 |
| Table 5-9: Dynamic Power Control of SAR Backoff State | 53 |
| Table 7-1: Mechanical and Environmental Specifications | 57 |

| | |
|---|-----|
| Table 8-1: Antenna Gain Specifications | 65 |
| Table 8-2: Collocated Radio Transmitter Specifications | 66 |
| Table A-1: Connector Pin Assignments | 67 |
| Table A-2: PCM/I2S Interface Signals | 68 |
| Table A-3: PCM Timing. | 69 |
| Table A-4: Master Transmitter with Data Rate = 1.536 MHz ($\pm 10\%$) | 70 |
| Table B-1: Antenna Requirements | 71 |
| Table B-2: GNSS Antenna Requirements. | 73 |
| Table C-1: Hardware Integration Design Considerations | 75 |
| Table D-1: Test Settings—UMTS Transmission Path | 82 |
| Table D-2: Test Settings—UMTS Receive Path. | 84 |
| Table D-3: Test Settings—LTE Receive Path | 86 |
| Table D-4: Extended AT Commands | 90 |
| Table G-1: LTE CA Inter-band Bandwidth Support. | 97 |
| Table G-2: LTE CA Intra-band (Contiguous) Bandwidth Support | 99 |
| Table G-3: LTE CA Intra-band (Non-contiguous) Bandwidth Support | 100 |
| Table H-1: Acronyms and Definitions | 101 |

»» | List of Figures

| | |
|--|----|
| Figure 3-1: System Block Diagram | 24 |
| Figure 3-2: Expanded RF Block Diagram | 25 |
| Figure 3-3: SIM Application Interface (applies to both SIM interfaces) | 32 |
| Figure 3-4: SIM Card Contacts (Contact View) | 32 |
| Figure 3-5: Recommended WAKE_N Connection. | 34 |
| Figure 3-6: Example LED | 35 |
| Figure 4-1: Module Connectors | 37 |
| Figure 5-1: Voltage/Temperature Monitoring State Machines | 50 |
| Figure 5-2: Signal Timing (W_DISABLE_N, and USB Enumeration) | 51 |
| Figure 7-1: Top View | 58 |
| Figure 7-2: Dimensioned View. | 58 |
| Figure 7-3: Sample Unit Label | 59 |
| Figure 7-4: Shield locations (Top view) | 60 |
| Figure 7-5: Copper Pad Location on Bottom Side of Module | 61 |
| Figure A-1: Timing—PCM_SYNC | 68 |
| Figure A-2: Timing—PCM Codec to Module. | 69 |
| Figure A-3: Timing—Module to PCM Codec. | 69 |
| Figure A-4: I2S Transmitter Timing | 70 |
| Figure 5-1: Device Placement in Module Tray. | 93 |
| Figure 5-2: Shipping Package | 93 |

1: Introduction

The Sierra Wireless MC7455 PCI Express Mini Card is a compact, lightweight, wireless modem that provides LTE, UMTS, and GNSS connectivity for M2M applications, notebook, ultrabook and tablet computers over several radio frequency bands.

Supported RF Bands

The modem, based on Qualcomm's MDM9230 baseband processor, supports data operation on LTE and UMTS networks over the bands described in Table 1-1, with LTE carrier aggregation (CA) as described in Table 1-2.

Table 1-1: Supported RF Bands

| Technology | Bands | | | | | | | | | | | | | | | Data Rates/Notes |
|---|---|---|---|---|---|---|---|----|----|----|----|----|----|-----|--|---|
| | 1 | 2 | 3 | 4 | 5 | 7 | 8 | 12 | 13 | 20 | 25 | 26 | 29 | 30 | 41 | |
| LTE | F | F | F | F | F | F | F | F | F | F | F | F | F | F | T | Data rates: <ul style="list-style-type: none"> Downlink (Cat 6): FDD: 300 Mbps TDD: 222 Mbps Uplink (Cat 6): FDD: 50 Mbps TDD: 26 Mbps Notes: <ul style="list-style-type: none"> Downlink MIMO support (2x2; 4x2) F=FDD; T= TDD |
| DC-HSPA+ HSPA+ HSPA UMTS | Y | Y | Y | Y | Y | | Y | | | | | | | N/A | Data rates: <ul style="list-style-type: none"> Downlink (Cat 24): Up to 42 Mbps Uplink (Cat 6): Up to 5.76 Mbps Notes: <ul style="list-style-type: none"> Diversity support | |
| GNSS | <ul style="list-style-type: none"> GPS: 1575.42 MHz GLONASS: 1602 MHz BeiDou: 1561.098 MHz Galileo¹: 1575.42 MHz | | | | | | | | | | | | | | | |

1. Future firmware upgrade

Table 1-2: Carrier Aggregation Combinations

| |
|------------------|
| 1 + 8 |
| 2 + 2/5/12/13/29 |
| 3 + 7/20 |
| 4 + 4/5/12/13/29 |
| 5 + 2/4/30 |
| 7 + 3/7/20 |
| 8 + 1 |
| 12 + 2/4/30 |
| 13 + 2/4 |
| 20 + 3/7 |
| 30 + 5/12 |
| 41 + 41 |

Physical Features

- Small form factor—conforms to type F2 as specified in *PCI Express Mini Card Electromechanical Specification Revision 1.2*.
- Ambient operating temperature range:
 - Class A (3GPP compliant): -30°C to +70°C
 - Class B (operational, non-3GPP compliant): -40°C to +85°C (reduced operating parameters required)

Important: *The internal module temperature (reported by AT!PCTEMP) must be kept below 90°C. For best performance, the internal module temperature should be kept below 80°C. Proper mounting, heat sinks, and active cooling may be required, depending on the integrated application.*

Application Interface Features

- USB interface (QMI) for Windows 7 and legacy Windows operating systems
- MBIM for Windows 8.1 and Windows 10
- AT command interface ([1] *AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)*, plus proprietary extended AT commands in [2] *AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*)
- Software Development Kits (SDK), including API (Application Program Interface) functions:
 - Windows 7, Windows 8.1, Windows 10
 - Linux

Note: OMA DM and FOTA support is operator-dependent.

- Support for active antenna control via dedicated antenna control signals (ANT_CTRL0:2)
- Dynamic power reduction support via software and dedicated signal (DPR)
- OMA DM (Open Mobile Alliance Device Management)
- FOTA (Firmware Over The Air)

Modem Features

- LTE / DC-HSPA+ / HSPA+ / HSPA / UMTS (WCDMA) operation
- Multiple (up to 16) cellular packet data profiles
- Traditional modem COM port support for AT commands
- USB suspend / resume
- Sleep mode for minimum idle power draw
- SIM application tool kit with proactive SIM commands
- Enhanced Operator Name String (EONS)
- Mobile-originated PDP context activation / deactivation
- Support QoS profile
 - Release 99 QoS negotiation—Background, Interactive, and Streaming
 - Release 97—Precedence Class, Reliability Class, Delay Class, Peak Throughput, Mean Throughput
- Static and Dynamic IP address. The network may assign a fixed IP address or dynamically assign one using DHCP (Dynamic Host Configuration Protocol).
- PAP and CHAP support
- PDP context type (IPv4, IPv6, or IPv4v6). IP Packet Data Protocol context supports dual IPv4v6.
- RFC1144 TCP/IP header compression

LTE Features

- Carrier aggregation:
 - DL LTE-FDD
 - 20 MHz intraband non-contiguous
 - 40 MHz interband
 - DL LTE-TDD
 - 40 MHz intraband contiguous and non-contiguous
 - 40 MHz interband
- CSG support (LTE Femto)
- LTE Advanced receivers (NLIC, eICIC, feICIC)
- Basic cell selection and system acquisition
 - PSS/SSS/MIB decode
 - SIB1–SIB16 decoding
- NAS/AS security procedures
 - Snow 3G/AES/ZUC security

- [CQI](#)/RI/PMI reporting
- Paging procedures
 - Paging in Idle and Connected mode
- Dedicated bearer
 - Network-initiated dedicated bearer
 - [UE](#)-initiated dedicated bearer
- Multiple PDN connections (IPv4 and IPv6 combinations), subject to operating system support.
- Connected mode intra-LTE mobility
- Idle mode intra-LTE mobility
- iRAT between LTE/3G for idle and connection release with redirection
- Detach procedure
 - Network-initiated detach with reattach required
 - Network-initiated detach followed by connection release

Short Message Service (SMS) Features

- Mobile-originated and mobile-terminated SMS over [IMS](#) for LTE
- Mobile-originated and mobile-terminated SMS over SGs for LTE

Position Location (GNSS)

- Customizable tracking session
- Automatic tracking session on startup
- Concurrent standalone GPS, GLONASS, and BeiDou
- Concurrent standalone Galileo (future firmware upgrade)
- Assisted GPS ([A-GPS](#)) SUPL1.0
- Assisted GPS/GLONASS SUPL2.0
- GPS/GLONASS on dedicated connector or diversity connector
- BeiDou on dedicated connector, or on diversity connector with reduced performance
- Galileo on dedicated connector or diversity connector (future firmware upgrade)

Supporting Documents

Several additional documents describe Mini Card design, usage, integration, and other features. See [References on page 95](#).

Accessories

The Universal Development Kit (UDK) is a hardware development platform for AirPrime MC-series modules. It contains hardware components for evaluating and developing with the module, including:

- Development board
- Cables
- Antennas (Additional antennas may be required to support all bands.)
- Initial allotment of support hours
- Other accessories

For instructions on setting up the UDK, see [3] *PCI Express Mini Card Dev Kit Quick Start Guide (Doc# 2130705)*.

For over-the-air LTE testing, ensure that suitable antennas are used. (Two antennas are required for this testing.)

Required Connectors

Table 1-3 describes the connectors used to integrate AirPrime MC-series modules into your host device.

Table 1-3: Required Host-Module Connectors¹

| Connector type | Description |
|----------------|---|
| RF cables | <ul style="list-style-type: none"> • Mate with Hirose U.FL connectors (model U.FL #CL331-0471-0-10) • Three connector jacks |
| EDGE (52-pin) | <ul style="list-style-type: none"> • Industry-standard mating connector • Some manufacturers include Tyco, Foxconn, Molex • Example: UDK board uses Molex 67910-0001 |
| SIM | <ul style="list-style-type: none"> • Industry-standard connector. Type depends on how host device exposes the SIM socket • Example: UDK board uses ITT CCM03-3518 |

1. Manufacturers/part numbers are for reference only and are subject to change. Choose connectors that are appropriate for your own design.

Ordering Information

To order, contact the Sierra Wireless Sales Desk at +1 (604) 232-1488 between 8 AM and 5 PM Pacific Time.

Integration Requirements

Sierra Wireless provides, in the document suite, guidelines for successful Mini Card integration and offers integration support services as necessary.

When integrating the MC7455 PCI-Express Mini Card, the following items need to be addressed:

- **Mounting**—Effect on temperature, shock, and vibration performance
- **Power supply**—Impact on battery drain and possible [RF](#) interference
- **Antenna location and type**—Impact on RF performance
- **Regulatory approvals**—As discussed in [Regulatory Compliance and Industry Certifications on page 63](#).
- **Service provisioning**—Manufacturing process
- **Software**—As discussed in [Software Interface on page 55](#).
- **Host Interface**—Compliance with interface voltage levels

2: Standards Compliance

The MC7455 Mini Card complies with the mandatory requirements described in the following standards. The exact set of requirements supported is network operator-dependent.

Table 2-1: Standards Compliance

| Technology | Standards |
|------------|---|
| LTE | <ul style="list-style-type: none">• 3GPP Release 11 |
| UMTS | <ul style="list-style-type: none">• 3GPP Release 9 |

3: Electrical Specifications

The system block diagram in [Figure 3-1 on page 24](#) represents the MC7455 module integrated into a host system. The module includes the following interfaces to the host:

- **Power**—Supplied to the module by the host.
- **W_DISABLE_N**—Input supplied to the module by the host to cause the module to either turn off/on or enter/exit low power mode (software configurable).
- **WAKE_N**—Signal used to wake the host when specific events occur.
- **WAN_LED_N**—Active-low **LED** drive signal provides an indication of RADIO ON state, either WAN or GNSS.
- **SYSTEM_RESET_N**—Active-low reset input.
- **Antenna**—Three U.FL **RF** connectors (main (Rx/Tx), GNSS, and auxiliary (diversity/MIMO/GNSS). For details, see [RF Specifications on page 37](#).
- **Antenna control**—Three signals that can be used to control external antenna switches.
- **Dynamic power control**—Signal used to adjust Tx power to meet FCC/CE SAR requirements. For details, see [Tx Power Control on page 53](#).
- **Dual SIM**—Supported through the interface connector. The **SIM** cavities / connectors must be placed on the host device for this feature.
- **USB**—USB 2.0 and USB 3.0 interfaces to the host for data, control, and status information.

The MC7455 has two main interface areas—the host I/O connector and the **RF** ports. Details of these interfaces are described in the sections that follow.

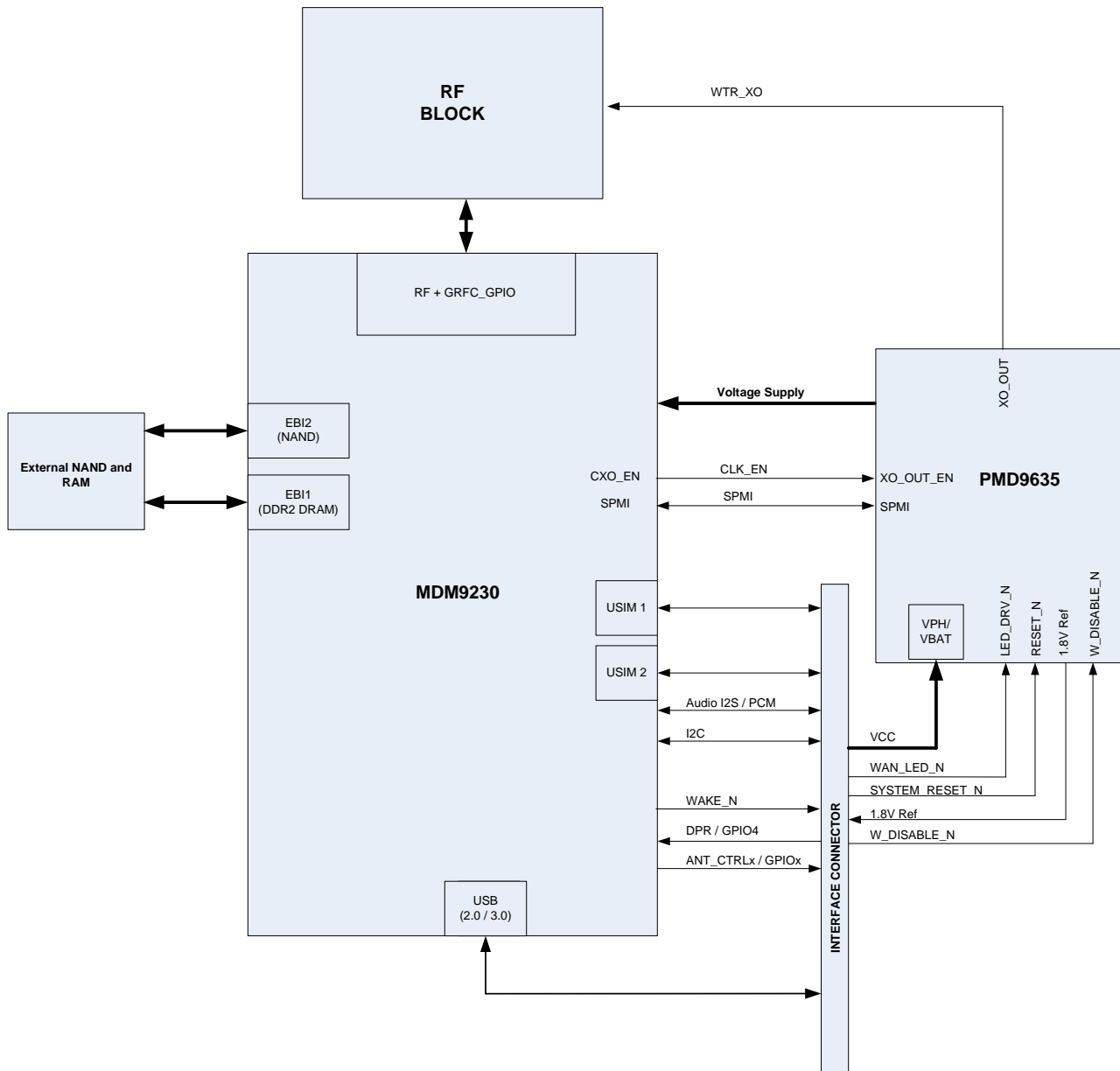


Figure 3-1: System Block Diagram

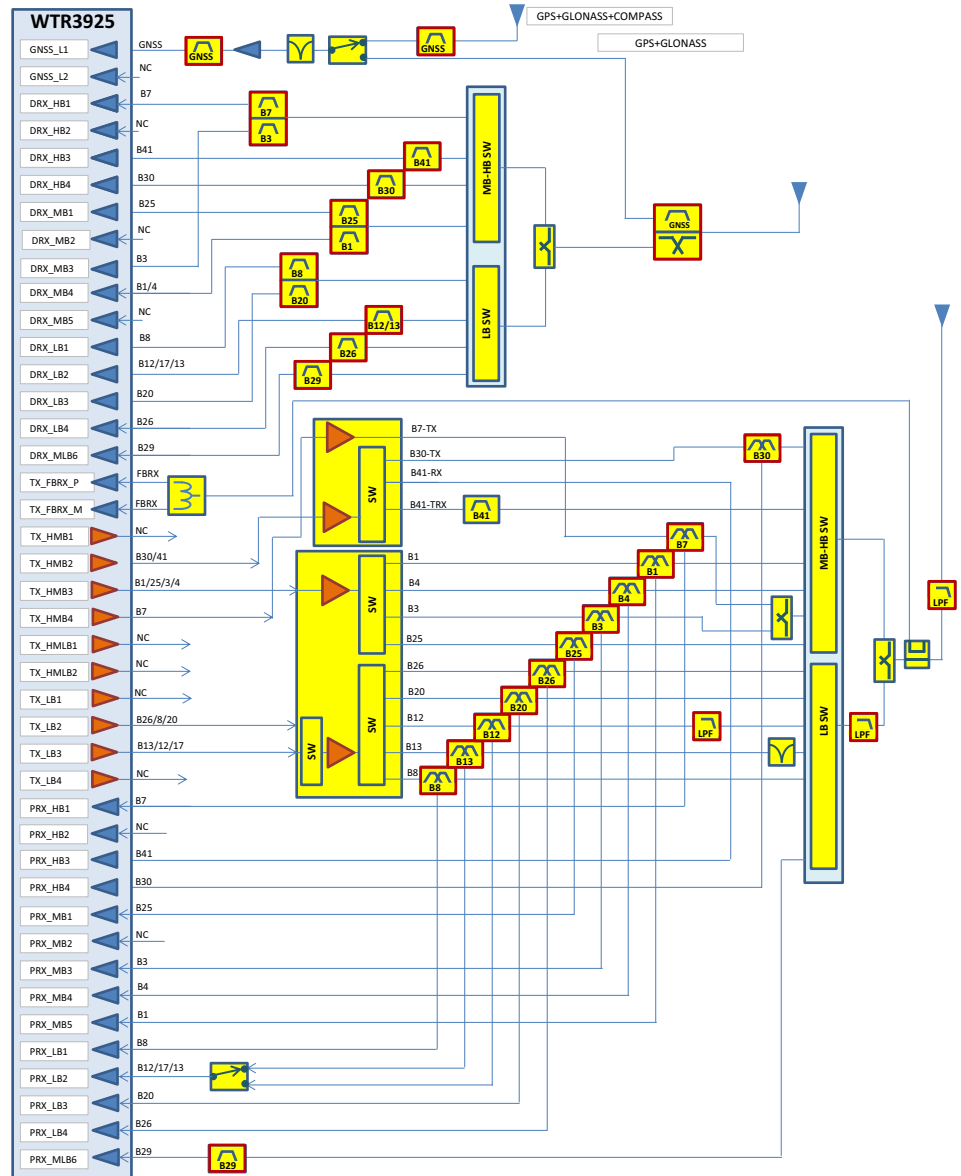


Figure 3-2: Expanded RF Block Diagram

Host Interface Pin Assignments

The MC7455 host I/O connector provides pins for power, serial communications, and control. Pin assignments are listed in [Table 3-1](#).

Refer to the following tables for pin details based on interface types:

- [Table 3-2, Power and Ground Specifications](#), on page 30
- [Table 3-3, USB Interfaces](#), on page 30
- [Table 3-4, SIM Interface Signals](#), on page 31
- [Table 3-5, Module Control Signals](#), on page 34

Note: On any given interface (USB, SIM, etc.), leave unused inputs and outputs as no-connects.

Note: The host should not drive any signals to the module until the power-on sequence is complete.

Table 3-1: Connector Pin Assignments¹

| Pin | Signal name | Pin type ² | Description | Direction ³ | Active state | Voltage levels (V) | | |
|------------|-------------------|-----------------------|---|------------------------|--------------|----------------------------------|----------------------------------|----------------------------------|
| | | | | | | Min | Typ | Max |
| 1 | WAKE_N | OC | Wake host | Output | Low | - | - | 0.10 |
| 2 | VCC | V | Power supply | Input | Power | 3.135 | 3.30 | 3.60 |
| 3 | ANT_CTRL0 / GPIO1 | - | (ANT_CTRL0) Customer-defined external switch control for multiple antennas | Output | High | 1.35 | 1.80 | 1.90 |
| | | | | Output | Low | 0 | - | 0.45 |
| | | | (GPIO1) General purpose I/O | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| Output Low | | 0.00 | | 0.45 | | | | |
| 4 | GND | V | Ground | Input | Power | - | 0 | - |
| 5 | ANT_CTRL1 / GPIO2 | - | (ANT_CTRL1) Customer-defined external switch control for multiple antennas | Output | High | 1.35 | 1.80 | 1.90 |
| | | | | Output | Low | 0 | - | 0.45 |
| | | | (GPIO2) General purpose I/O | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| Output Low | | 0.00 | | 0.45 | | | | |
| 6 | NC | - | No connect | - | - | - | - | - |
| 7 | USIM2_RST | - | SIM 2 Reset | Output | Low | 0 | - | 0.45 |
| | | | | | High | 2.55 (3V SIM) 1.35 (1.8V SIM) | - | 3.10 (3V SIM) 1.90 (1.8V SIM) |
| 8 | USIM_PWR | - | SIM VCC supply | Output | Power | 2.90 (3V SIM) 1.75 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.85 (1.8V SIM) |
| 9 | GND | V | Ground | Input | Power | - | 0 | - |

Table 3-1: Connector Pin Assignments¹ (Continued)

| Pin | Signal name | Pin type ² | Description | Direction ³ | Active state | Voltage levels (V) | | |
|-----|-----------------------------|-----------------------|--------------------------------|------------------------|--------------|------------------------------------|----------------------------------|----------------------------------|
| | | | | | | Min | Typ | Max |
| 10 | USIM_DATA | - | SIM IO pin | Input | Low | -0.30 (3V SIM) -0.30 (1.8V SIM) | - | 0.60 (3V SIM) 0.35 (1.8V SIM) |
| | | | | | High | 2.10 (3V SIM) 1.17 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.30 (3V SIM) 2.10 (1.8V SIM) |
| | | | | Output | Low | 0 | - | 0.40 |
| | | | | | High | 2.55 (3V SIM) 1.35 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.90 (1.8V SIM) |
| 11 | VREF_1.8V ⁴ | - | 1.8V reference voltage output | Output | Power | 1.75 | 1.80 | 1.85 |
| 12 | USIM_CLK | - | SIM Clock | Output | Low | 0 | - | 0.45 |
| | | | | | High | 2.55 (3V SIM) 1.35 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.90 (1.8V SIM) |
| 13 | USIM2_PWR | - | SIM 2 VCC supply | Output | Power | 2.90 (3V SIM) 1.75 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.85 (1.8V SIM) |
| 14 | USIM_RST | - | SIM Reset | Output | Low | 0 | - | 0.45 |
| | | | | | High | 2.55 (3V SIM) 1.35 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.90 (1.8V SIM) |
| 15 | GND | V | Ground | Input | Power | - | 0 | - |
| 16 | NC | - | No connect | - | - | - | - | - |
| 17 | USIM2_CLK | - | SIM 2 Clock | Output | Low | 0 | - | 0.45 |
| | | | | | High | 2.55 (3V SIM) 1.35 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.90 (1.8V SIM) |
| 18 | GND | V | Ground | Input | Power | - | 0 | - |
| 19 | USIM2_DATA | - | SIM 2 IO pin | Input | Low | -0.30 (3V SIM) -0.30 (1.8V SIM) | - | 0.60 (3V SIM) 0.35 (1.8V SIM) |
| | | | | | High | 2.10 (3V SIM) 1.17 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.30 (3V SIM) 2.10 (1.8V SIM) |
| | | | | Output | Low | 0 | - | 0.40 |
| | | | | | High | 2.55 (3V SIM) 1.35 (1.8V SIM) | 3.00 (3V SIM) 1.80 (1.8V SIM) | 3.10 (3V SIM) 1.90 (1.8V SIM) |
| 20 | W_DISABLE_N ⁵ | PU | Module power state control | Input | Low | -0.30 | - | 0.40 |
| 21 | GND | V | Ground | Input | Power | - | 0 | - |
| 22 | SYSTEM_RESET_N ⁶ | OC | Reset | Input | Low | -0.30 | - | 0.63 |
| 23 | USB3.0_TX- | | USB 3.0 Transmit Data negative | Output | Differential | - | - | - |

Table 3-1: Connector Pin Assignments¹ (Continued)

| Pin | Signal name | Pin type ² | Description | Direction ³ | Active state | Voltage levels (V) | | |
|-----|---|-----------------------|--|------------------------|--------------|--------------------|------|------|
| | | | | | | Min | Typ | Max |
| 24 | VCC | V | Power supply | Input | Power | 3.135 | 3.30 | 3.60 |
| 25 | USB3.0_TX+ | | USB 3.0 Transmit Data positive | Output | Differential | - | - | - |
| 26 | GND | V | Ground | Input | Power | - | 0 | - |
| 27 | GND | V | Ground | Input | Power | - | 0 | - |
| 28 | NC | - | No connect | - | - | - | - | - |
| 29 | GND | V | Ground | Input | Power | - | 0 | - |
| 30 | NC (For audio interface pin usage, see Audio Support on page 67.) | | Reserved— Host must not repurpose this pin. | | | | | |
| 31 | USB3.0_RX- | | USB 3.0 Receive Data negative | Input | Differential | - | - | - |
| 32 | NC (For audio interface pin usage, see Audio Support on page 67.) | | Reserved— Host must not repurpose this pin. | | | | | |
| 33 | USB3.0_RX+ | | USB 3.0 Receive Data positive | Input | Differential | - | - | - |
| 34 | GND | V | Ground | Input | Power | - | 0 | - |
| 35 | GND | V | Ground | Input | Power | - | 0 | - |
| 36 | USB_D- | - | USB data negative | Input/Output | Differential | - | - | - |
| 37 | GND | V | Ground | Input | Power | - | 0 | - |
| 38 | USB_D+ | - | USB data positive | Input/Output | Differential | - | - | - |
| 39 | VCC | V | Power supply | Input | Power | 3.135 | 3.30 | 3.60 |
| 40 | GND | V | Ground | Input | Power | - | 0 | - |
| 41 | VCC | V | Power supply | Input | Power | 3.135 | 3.30 | 3.60 |
| 42 | WAN_LED_N | OC | LED Driver | Output | Low | 0 | - | 0.15 |
| 43 | GND | V | Ground | Input | Power | - | 0 | - |

Table 3-1: Connector Pin Assignments¹ (Continued)

| Pin | Signal name | Pin type ² | Description | Direction ³ | Active state | Voltage levels (V) | | |
|------------|---|-----------------------|---|------------------------|--------------|--------------------|------|------|
| | | | | | | Min | Typ | Max |
| 44 | ANT_CTRL2 / GPIO3 | - | (ANT_CTRL2) Customer-defined external switch control for multiple antennas | Output | High | 1.35 | 1.80 | 1.90 |
| | | | | Output | Low | 0 | - | 0.45 |
| | | | (GPIO3) General purpose I/O | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| Output Low | | 0.00 | | 0.45 | | | | |
| 45 | NC (For audio interface pin usage, see Audio Support on page 67.) | | Reserved— Host must not repurpose this pin. | | | | | |
| 46 | DPR / GPIO4 | - | (DPR) Dynamic power control | Input | High | 1.17 | 1.80 | 2.10 |
| | | | | Input | Low | -0.30 | - | 0.63 |
| | | | (GPIO4) General purpose I/O | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| Output Low | | 0.00 | | 0.45 | | | | |
| 47 | NC (For audio interface pin usage, see Audio Support on page 67.) | | Reserved— Host must not repurpose this pin. | | | | | |
| 48 | NC | - | No connect | - | - | - | - | - |
| 49 | NC (For audio interface pin usage, see Audio Support on page 67.) | | Reserved— Host must not repurpose this pin. | | | | | |
| 50 | GND | V | Ground | Input | Power | - | 0 | - |
| 51 | NC (For audio interface pin usage, see Audio Support on page 67.) | | Reserved— Host must not repurpose this pin. | | | | | |
| 52 | VCC | V | Power supply | Input | Power | 3.135 | 3.30 | 3.60 |

1. The host should leave all 'NC' ('no connect') pins unconnected.
2. A—Analog; I—Input; NP—No pull; O—Digital output; OC—Open Collector; PU—Digital input (internal pull up); PD—Digital output (internal pull down); V—Power or ground
3. Signal directions are from module's point of view (e.g. 'Output' from module to host, 'Input' to module from host.)
4. To avoid adverse effects on module operation, do not draw more than 10 mA current on pin 11.
5. Sierra Wireless recommends that the host implement an open collector driver where a Low signal will turn the module off or enter low power mode, and a high signal will turn the module on or leave low power mode.
6. The module must not be plugged into a port that supports PCI Express—the pin is used by a PCIE signal, which can cause the module to be in reset state or occasionally reset.

Power Supply

The host provides power to the MC7455 through multiple power and ground pins as summarized in [Table 3-2](#).

The host must provide safe and continuous power at all times; the module does not have an independent power supply, or protection circuits to guard against electrical issues.

Table 3-2: Power and Ground Specifications

| Name | Pins | Specification | Min | Typ | Max | Units |
|------|--|----------------|--|-----|-----|------------------|
| VCC | 2, 24, 39, 41, 52 | Voltage range | See Table 3-1 on page 26 . | | | |
| | | Ripple voltage | - | - | 100 | mV _{pp} |
| GND | 4, 9, 15, 18, 21, 26, 27, 29, 34, 35, 37, 40, 43, 50 | - | - | 0 | - | V |

USB Interface

Important: Host support for USB 2.0 signals is required.

Important: Host support for USB 3.0 signals is optional, but if supported then the host must also support fallback to USB 2.0.

The device supports USB 2.0 and USB 3.0 interfaces for communication between the host and module.

The interfaces comply with the [10] *Universal Serial Bus Specification, Rev 2.0* and [11] *Universal Serial Bus Specification, Rev 3.0*, and the host device must be designed to the same standards (subject to details shown in [Table 3-3](#) below). (Note: When designing the host device, careful PCB layout practices must be followed.)

Table 3-3: USB Interfaces

| | Name | Pin | Description |
|---------|-------------------------|-----|------------------------|
| USB 2.0 | USB_D- | 36 | USB data negative |
| | USB_D+ | 38 | USB data positive |
| USB 3.0 | USB3.0_TX ⁻¹ | 23 | Transmit data negative |
| | USB3.0_TX ⁺¹ | 25 | Transmit data positive |
| | USB3.0_RX ⁻¹ | 31 | Receive data negative |
| | USB3.0_RX ⁺¹ | 33 | Receive data positive |

1. Signal directions (Tx/Rx) are from device's point of view.

USB Throughput Performance

This device has been designed to achieve optimal performance and maximum throughput using USB superspeed mode (USB 3.0). Although the device may operate with a high speed host, throughput performance will be on an “as is” basis and needs to be characterized by the [OEM](#). Note that throughput will be reduced and may vary significantly based on [packet](#) size, host interface, and [firmware](#) revision.

User-developed Drivers

Details for user-developed USB drivers are described in [4] *AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)*.

SIM Interface

Note: Host support for SIM interface signals is required.

Note: Sprint requires the use of ISIM. USIM and CSIM are not supported per Sprint implementation.

The module supports up to two SIMs (Subscriber Identity Module) (1.8 V or 3 V). Each SIM holds information for a unique account, allowing users to optimize their use of each account on multiple devices.

The [SIM](#) pins ([Table 3-4](#)) provide the connections necessary to interface to SIM sockets located on the host device as shown in [Figure 3-3 on page 32](#). Voltage levels over this interface comply with 3GPP standards.

The types of SIM connectors used depends on how the host device exposes the SIM sockets.

Table 3-4: SIM Interface Signals

| SIM | Name | Pin | Description | SIM contact number ¹ | Notes |
|-----------|------------|-----|----------------|---------------------------------|--|
| Primary | USIM_PWR | 8 | SIM voltage | 1 | Power supply for SIM |
| | USIM_DATA | 10 | Data I/O | 7 | Bi-directional SIM data line |
| | USIM_CLK | 12 | Serial clock | 3 | Serial clock for SIM data |
| | USIM_RST | 14 | Reset | 2 | Active low SIM reset |
| | USIM_GND | | Ground | 5 | Ground reference USIM_GND is common to module ground |
| Secondary | USIM2_PWR | 13 | SIM voltage | 2 | Power supply for SIM 2 |
| | USIM2_DATA | 19 | Data I/O | 3 | Bi-directional SIM 2 data line |
| | USIM2_CLK | 17 | Serial clock | 7 | Serial clock for SIM 2 data |
| | USIM2_RST | 7 | Reset | 1 | Active low SIM 2 reset |
| | USIM2_GND | | SIM indication | - | Ground reference USIM2_GND is common to module ground |

1. See [Figure 3-4 on page 32](#) for SIM card contacts.

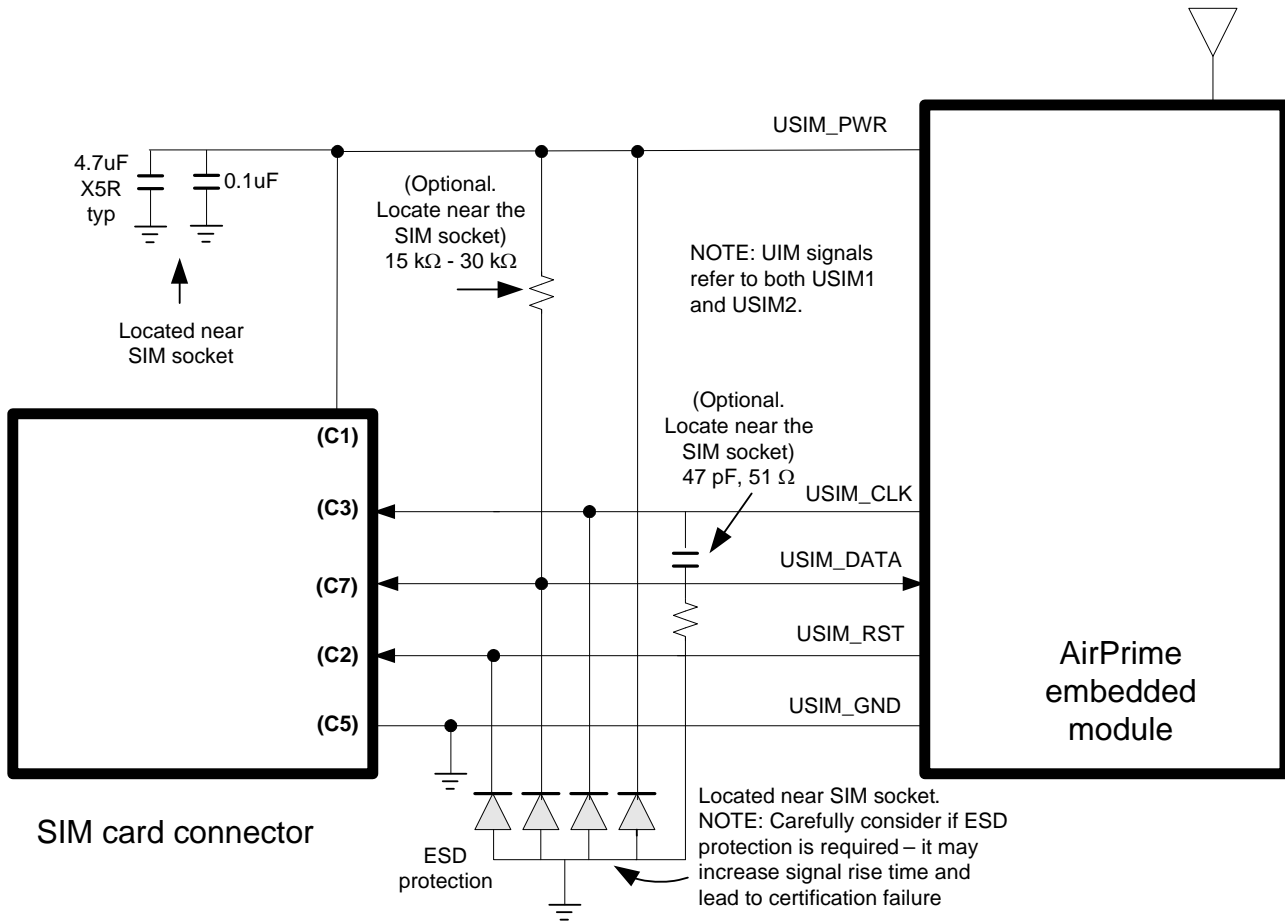


Figure 3-3: SIM Application Interface (applies to both SIM interfaces)

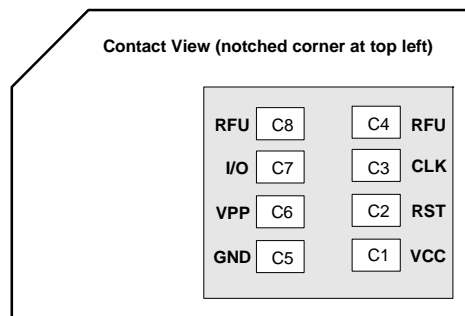


Figure 3-4: SIM Card Contacts (Contact View)

SIM Implementation

Note: For interface design requirements, refer to ETSI TS 102 230 V5.5.0, section 5.2.

When designing the remote SIM interface, you *must* make sure that SIM signal integrity is not compromised.

Some design recommendations include:

- Total impedance of the VCC and GND connections to the SIM, measured at the module connector, should be less than $1\ \Omega$ to minimize voltage drop (includes any trace impedance and lumped element components—inductors, filters, etc.).
- Position the SIM connector ≤ 10 cm from the module. If a longer distance is required because of the host device design, use a shielded wire assembly—connect one end as close as possible to the SIM connector and the other end as close as possible to the module connector. The shielded assembly may help shield the SIM interface from system noise.
- Reduce crosstalk on the USIM_DATA and USIM2_DATA lines to reduce the risk of failures during GCF approval testing.
- Avoid routing the clock and data lines for each SIM (USIM_CLK/USIM_DATA, USIM2_CLK/USIM2_DATA) in parallel over distances > 2 cm—cross-coupling of a clock and data line pair can cause failures.
- 3GPP has stringent requirements for I/O rise time ($< 1\ \mu\text{s}$), signal level limits, and noise immunity—consider this carefully when developing your PCB layout.
 - Keep signal rise time $< 1\ \mu\text{s}$ —keep SIM signals as short as possible, and keep very low capacitance traces on the data and clock signals (USIM_CLK, USIM_DATA, USIM2_CLK, USIM2_DATA). High capacitance increases signal rise time, potentially causing your device to fail certification tests.
- Add external pull-up resistors ($15\ \text{k}\Omega$ – $30\ \text{k}\Omega$), if required, between the data and power lines for each SIM (USIM_DATA/USIM_PWR, USIM2_DATA/USIM2_PWR) to optimize the signal rise time.
- VCC line should be decoupled close to the SIM socket.
- SIM is specified to run up to 5 MHz (SIM clock rate). Take note of this speed in the placement and routing of the SIM signals and connectors.
- You must decide whether additional ESD protection is required for your product, as it is dependent on the application, mechanical enclosure, and SIM connector design. The SIM pins will require additional ESD protection if they are exposed to high ESD levels (i.e. can be touched by a user).
- Putting optional decoupling capacitors on the SIM power lines (USIM_PWR, USIM2_PWR) near the SIM sockets is recommended—the longer the trace length (impedance) from the socket to the module, the greater the capacitance requirement to meet compliance tests.
- Putting an optional series capacitor and resistor termination (to ground) on the clock lines (USIM_CLK, USIM2_CLK) at the SIM sockets to reduce EMI and increase signal integrity is recommended if the trace length between the SIM socket and module is long— $47\ \text{pF}$ and $50\ \Omega$ resistor are recommended.
- Test your first prototype host hardware with a Comprion IT³ SIM test device at a suitable testing facility.

Control Interface (Signals)

The MC7455 provides signals for:

- Waking the host when specific events occur
- Host control of module power
- LED driver output

These signals are summarized in [Table 3-5](#) and paragraphs that follow.

Table 3-5: Module Control Signals

| Name | Pin | Description | Type ¹ |
|-------------|-----|----------------------------|-------------------|
| WAKE_N | 1 | Wake host | OC |
| W_DISABLE_N | 20 | On/off signal ² | PU |
| WAN_LED_N | 42 | LED driver | OC |

1. OC—Open Collector; PU—Digital pin Input, internal pull up
2. W_DISABLE_N causes the module to either turn off/on or enter/leave low power mode (software configurable).

WAKE_N — Wake Host

Note: Host support for WAKE_N is optional.

The module uses WAKE_N to wake the host when specific events occur.

The host must provide a 5 kΩ–100 kΩ pullup resistor that considers total line capacitance (including parasitic capacitance) such that when WAKE_N is deasserted, the line will rise to 3.3 V (Host power rail) in < 100 ns.

See [Figure 3-5 on page 34](#) for a recommended implementation.

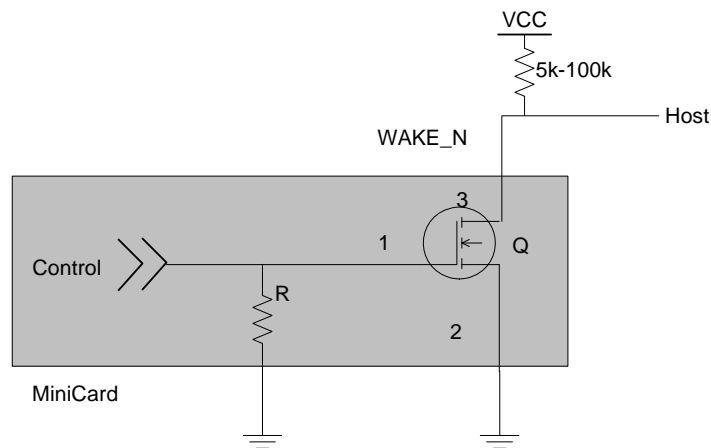


Figure 3-5: Recommended WAKE_N Connection

W_DISABLE_N — Wireless Disable

Note: Host support for W_DISABLE_N is required.

The host uses W_DISABLE_N to cause the module to either turn off/on or enter/leave low power mode, as described in [Table 3-6](#).

For timing details, see [Power-On/Off Timing on page 51](#).

Table 3-6: W_DISABLE_N Usage

| Name | Pin | Description/notes |
|-------------|-----|---|
| W_DISABLE_N | 20 | <p>Powers the module on/off (or enters/leaves low power mode)¹.</p> <ul style="list-style-type: none"> Leave as not connected or drive HIGH to keep the modem always on Drive LOW to turn the module off (or enter low power mode). An AT command may be used to configure this signal so the module enters low power mode instead of powering off. |

1. Sierra Wireless recommends that the host implement an open collector driver where a Low signal will turn the module off or enter low power mode, and a high signal will turn the module on or leave low power mode.

WAN_LED_N—LED Output

Note: Host support for WAN_LED_N is optional.

The module drives the LED output according to *[9] PCI Express Mini Card Electromechanical Specification Revision 2.1*.

Note: The LED configuration is customizable. Contact your Sierra Wireless account representative for details.

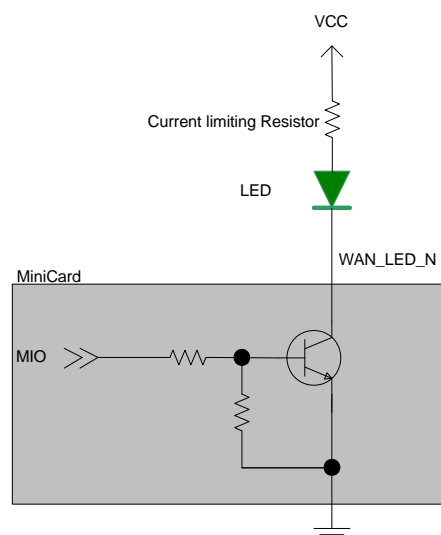


Figure 3-6: Example LED

SYSTEM_RESET_N—Reset Input

Note: Host support for SYSTEM_RESET_N is optional.

SYSTEM_RESET_N has an internal 1.8 V internal pull up that requires an open collector input from the host. Set this signal to active low to reset the device. Note that the minimum pulse width is 2 s.

Note: The module must not be plugged into a port that supports PCI Express—SYSTEM_RESET_N is carried on a pin that is used for a PCIE signal, which can cause the module to be in reset state or occasionally reset.

Antenna Control

Note: Host support for antenna control signals is optional.

The MC7455 Mini Card provides three output signals (listed in [Table 3-7](#)) that may be used for host designs that incorporate tunable antennas..

Customers can configure these signals as appropriate for the operating band(s) using the command AT!ANTSEL. (See [2] *AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)* for details.)

Note:

- To avoid detuning the PCC band, customers must make sure there are no GPIO state conflicts between the PCC and SCC for all supported CA combinations.

Table 3-7: Antenna Control Signals

| Name | Pin | Description |
|-----------|-----|---|
| ANT_CTRL0 | 3 | Customer-defined external switch control for tunable antennas |
| ANT_CTRL1 | 5 | |
| ANT_CTRL2 | 44 | |

4: RF Specifications

The MC7455 includes three RF connectors for use with host-supplied antennas:

- Main RF connector—Tx/Rx path
- GNSS RF connector—Dedicated GPS, GLONASS, BeiDou, and Galileo
- Auxiliary RF connector—Diversity, MIMO, GPS, GLONASS, and Galileo

The module does not have integrated antennas.

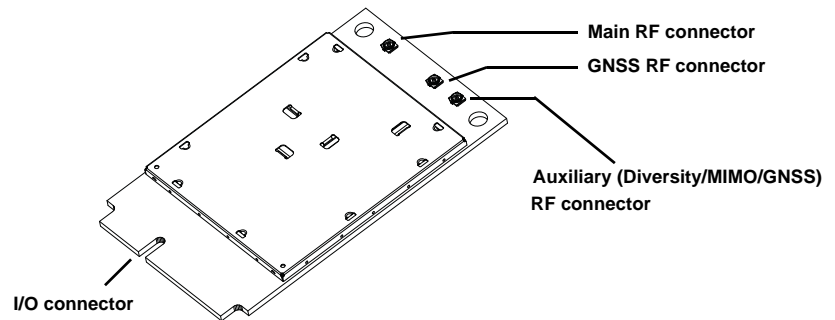


Figure 4-1: Module Connectors

RF Connections

When attaching antennas to the module:

- Use Hirose U.FL connectors (3 mm x 3 mm, low profile; model U.FL #CL331-0471-0-10) to attach antennas to connection points on the module, as shown in [Figure 4-1](#) on page 37.
- Match coaxial connections between the module and the antenna to 50 Ω .
- Minimize RF cable losses to the antenna; the recommended maximum cable loss for antenna cabling is 0.5 dB.
- To ensure best thermal performance, mounting holes must be used to attach (ground) the device to the main PCB ground or a metal chassis.

Note: If the antenna connection is shorted or open, the modem will not sustain permanent damage.

Shielding

The module is fully shielded to protect against EMI and the shield must not be removed.

*Note: To **disconnect** the antenna, make sure you use the Hirose U.FL connector removal tool (P/N UFL-LP-N-2(01)) to prevent damage to the module or coaxial cable assembly.*

Antenna and Cabling

When selecting the antenna and cable, it is critical to RF performance to optimize antenna gain and cable loss.

Note: For detailed electrical performance criteria, see [Appendix B: Antenna Specification](#) on page 71.

Choosing the Correct Antenna and Cabling

When matching antennas and cabling:

- The antenna (and associated circuitry) should have a nominal impedance of 50 Ω with a recommended return loss of better than 10 dB across each frequency band of operation.
- The system gain value affects both radiated power *and* regulatory (FCC, IC, CE, etc.) test results.

Designing Custom Antennas

Consider the following points when designing custom antennas:

- A skilled RF engineer should do the development to ensure that the RF performance is maintained.
- If both CDMA and UMTS modules will be installed in the same platform, you may want to develop separate antennas for maximum performance.

Determining the Antenna's Location

When deciding where to put the antennas:

- Antenna location may affect RF performance. Although the module is shielded to prevent interference in most applications, the placement of the antenna is still very important—if the host device is insufficiently shielded, high levels of broadband noise or spurious interference can degrade the module's performance.
- Connecting cables between the module and the antenna must have 50 Ω impedance. If the impedance of the module is mismatched, RF performance is reduced significantly.
- Antenna cables should be routed, if possible, away from noise sources (switching power supplies, LCD assemblies, etc.). If the cables are near the noise sources, the noise may be coupled into the RF cable and into the antenna. See [Interference From Other Wireless Devices](#) on page 39.

Disabling the Diversity Antenna

Use the AT command `!RXDEN=0` to disable receive diversity or `!RXDEN=1` to enable receive diversity.

Note: A diversity antenna is used to improve connection quality and reliability through redundancy. Because two antennas may experience different interference effects (signal distortion, delay, etc.), when one antenna receives a degraded signal, the other may not be similarly affected.

Ground Connection

When connecting the module to system ground:

- Prevent noise leakage by establishing a very good ground connection to the module through the host connector.
- Connect to system ground using the two mounting holes at the top of the module (shown in [Figure 4-1](#) on page 37).
- Minimize ground noise leakage into the RF.
Depending on the host board design, noise could *potentially* be coupled to the module from the host board. This is mainly an issue for host designs that have signals traveling along the length of the module, or circuitry operating at both ends of the module interconnects.

Interference and Sensitivity

Several interference sources can affect the module's RF performance (RF desense). Common sources include power supply noise and device-generated RF.

RF desense can be addressed through a combination of mitigation techniques ([Methods to Mitigate Decreased Rx Performance on page 40](#)) and radiated sensitivity measurement ([Radiated Sensitivity Measurement on page 40](#)).

Note: The MC7455 is based on ZIF (Zero Intermediate Frequency) technologies. When performing EMC (Electromagnetic Compatibility) tests, there are no IF (Intermediate Frequency) components from the module to consider.

Interference From Other Wireless Devices

Wireless devices operating inside the host device can cause interference that affects the module.

To determine the most suitable locations for antennas on your host device, evaluate each wireless device's radio system, considering the following:

- Any harmonics, sub-harmonics, or cross-products of signals generated by wireless devices that fall in the module's Rx range may cause spurious response, resulting in decreased Rx performance.
- The Tx power and corresponding broadband noise of other wireless devices may overload or increase the noise floor of the module's receiver, resulting in Rx desense.

The severity of this interference depends on the closeness of the other antennas to the module's antenna. To determine suitable locations for each wireless device's antenna, thoroughly evaluate your host device's design.

Host-generated RF Interference

All electronic computing devices generate RF interference that can negatively affect the receive sensitivity of the module.

Proximity of host electronics to the antenna in wireless devices can contribute to decreased Rx performance. Components that are most likely to cause this include:

- Microprocessor and memory
- Display panel and display drivers
- Switching-mode power supplies

Device-generated RF Interference

The module can cause interference with other devices. Wireless devices such as AirPrime embedded modules transmit in bursts (pulse transients) for set durations (RF burst frequencies). Hearing aids and speakers convert these burst frequencies into audible frequencies, resulting in audible noise.

Methods to Mitigate Decreased Rx Performance

It is important to investigate sources of localized interference early in the design cycle. To reduce the effect of device-generated RF on Rx performance:

- Put the antenna as far as possible from sources of interference. The drawback is that the module may be less convenient to use.
- Shield the host device. The module itself is well shielded to avoid external interference. However, the antenna cannot be shielded for obvious reasons. In most instances, it is necessary to employ shielding on the components of the host device (such as the main processor and parallel bus) that have the highest RF emissions.
- Filter out unwanted high-order harmonic energy by using discrete filtering on low frequency lines.
- Form shielding layers around high-speed clock traces by using multi-layer PCBs.
- Route antenna cables away from noise sources.

Radiated Spurious Emissions (RSE)

When designing an antenna for use with AirPrime embedded modules, the host device with an AirPrime embedded module must satisfy any applicable standards/local regulatory bodies for radiated spurious emission (RSE) for receive-only mode and for transmit mode (transmitter is operating).

Note that antenna impedance affects radiated emissions, which must be compared against the conducted 50-ohm emissions baseline. (AirPrime embedded modules meet the 50-ohm conducted emissions requirement.)

Radiated Sensitivity Measurement

A wireless host device contains many noise sources that contribute to a reduction in Rx performance.

To determine the extent of any receiver performance desensitization due to self-generated noise in the host device, over-the-air (OTA) or radiated testing is required. This testing can be performed by Sierra Wireless or you can use your own OTA test chamber for in-house testing.

Sierra Wireless' Sensitivity Testing and Desensitization Investigation

Although AirPrime embedded modules are designed to meet network operator requirements for receiver performance, they are still susceptible to various performance inhibitors.

As part of the Engineering Services package, Sierra Wireless offers modem OTA sensitivity testing and desensitization (desense) investigation. For more information, contact your account manager or the Sales Desk (see [Contact Information on page 4](#)).

Note: Sierra Wireless has the capability to measure TIS (Total Isotropic Sensitivity) and TRP (Total Radiated Power) according to CTIA's published test procedure.

Sensitivity vs. Frequency

For UMTS bands, sensitivity is defined as the input power level in dBm that produces a BER (Bit Error Rate) of 0.1%. Sensitivity should be measured at all UMTS frequencies across each band.

For LTE bands, sensitivity is defined as the RF level at which throughput is 95% of maximum.

Supported Frequencies

The MC7455 supports:

- Multiple-band LTE—See [Table 4-1 on page 42](#) (supported bands) and [Table 4-2 on page 42](#) (LTE bandwidth support).
- LTE Advanced carrier aggregation—See [Table 1-2 on page 16](#). For detailed carrier aggregation bandwidth support, see [LTE CA Bandwidth Support on page 99](#).
- Multiple-band WCDMA/HSPA/HSPA+/DC-HSPA+—See [Table 4-3 on page 43](#).
- Multiple-band WCDMA receive diversity
- GPS, GLONASS, BeiDou, Galileo—See [Table 4-7 on page 45](#).
- Inter-RAT and inter-frequency cell reselection and handover between supported frequency bands

Table 4-1: LTE Frequency Bands

| Band | Frequency (Tx) | Frequency (Rx) |
|---------|---------------------|----------------|
| Band 1 | 1920–1980 MHz | 2110–2170 MHz |
| Band 2 | 1850–1910 MHz | 1930–1990 MHz |
| Band 3 | 1710–1785 | 1805–1880 MHz |
| Band 4 | 1710–1755 | 2110–2155 MHz |
| Band 5 | 824–849 MHz | 869–894 MHz |
| Band 7 | 2500–2570 MHz | 2620–2690 MHz |
| Band 8 | 880–915 MHz | 925–960 MHz |
| Band 12 | 699–716 MHz | 729–746 MHz |
| Band 13 | 777–787 MHz | 746–756 MHz |
| Band 20 | 832–862 MHz | 791–821 MHz |
| Band 25 | 1850–1915 MHz | 1930–1995 MHz |
| Band 26 | 814–849 MHz | 859–894 MHz |
| Band 29 | n/a | 717–728 MHz |
| Band 30 | 2305–2315 MHz | 2350–2360 MHz |
| Band 41 | 2496–2690 MHz (TDD) | |

Table 4-2: LTE Bandwidth support¹

| Band | 1.4 MHz | 3 MHz | 5 MHz | 10 MHz | 15 MHz | 20 MHz |
|---------|---------|-------|----------------|----------------|----------------|------------------|
| Band 1 | ✗ | ✗ | ✓ | ✓ | ✓ | ✓ |
| Band 2 | ✓ | ✓ | ✓ | ✓ | ✓ ² | ✓ ² |
| Band 3 | ✓ | ✓ | ✓ | ✓ | ✓ ² | ✓ ² |
| Band 4 | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ |
| Band 5 | ✓ | ✓ | ✓ | ✓ ² | ✗ | ✗ |
| Band 7 | ✗ | ✗ | ✓ | ✓ | ✓ ³ | ✓ ^{2,3} |
| Band 8 | ✓ | ✓ | ✓ | ✓ ² | ✗ | ✗ |
| Band 12 | ✓ | ✓ | ✓ ² | ✓ ² | ✗ | ✗ |
| Band 13 | ✗ | ✗ | ✓ ² | ✓ ² | ✗ | ✗ |
| Band 20 | ✗ | ✗ | ✓ | ✓ ² | ✓ ² | ✓ ² |
| Band 25 | ✓ | ✓ | ✓ | ✓ | ✓ ² | ✓ ² |
| Band 26 | ✓ | ✓ | ✓ | ✓ ² | ✓ ² | ✗ |

Table 4-2: LTE Bandwidth support¹

| Band | 1.4 MHz | 3 MHz | 5 MHz | 10 MHz | 15 MHz | 20 MHz |
|---------|---------|-------|-------|----------------|--------|--------|
| Band 30 | ✗ | ✗ | ✓ | ✓ ² | ✗ | ✗ |
| Band 41 | ✗ | ✗ | ✓ | ✓ | ✓ | ✓ |

1. Table contents are derived from 3GPP TS 36.521-1 v12.6.0, table 5.4.2.1-1.
2. Bandwidth for which a relaxation of the specified UE receiver sensitivity requirement (Clause 7.3 of 3GPP TS 36.521-1 v12.6.0) is allowed.
3. Bandwidth for which uplink transmission bandwidth can be restricted by the network for some channel assignments in FDD/TDD co-existence scenarios in order to meet unwanted emissions requirements (Clause 6.6.3.2 of 3GPP TS 36.521-1 v12.6.0).

Table 4-3: WCDMA Frequency Bands

| Band ¹ | Frequency (Tx) | Frequency (Rx) |
|-------------------|----------------|----------------|
| Band 1 | 1920–1980 MHz | 2110–2170 MHz |
| Band 2 | 1850–1910 MHz | 1930–1990 MHz |
| Band 3 | 1710–1785 MHz | 1805–1880 MHz |
| Band 4 | 1710–1755 MHz | 2110–2155 MHz |
| Band 5 | 824–849 MHz | 869–894 MHz |
| Band 8 | 880–915 MHz | 925–960 MHz |

1. WCDMA channel spacing is 5 MHz, but this can be adjusted to optimize performance in a particular deployment scenario.

Conducted Rx Sensitivity / Tx Power

Note: All values in the following tables are preliminary, pending transceiver matching and testing.

Table 4-4: Conducted Rx (Receive) Sensitivity—LTE Bands

| LTE bands | | Conducted Rx sensitivity (dBm) | | | |
|-------------|------------------------------------|--------------------------------|---------------------|----------------|--------------------------------|
| | | Primary (Typical) | Secondary (Typical) | SIMO (Typical) | SIMO ¹ (Worst case) |
| LTE Band 1 | Full RB BW: 10 MHz ² | -97.5 | -97.0 | -100.5 | -96.3 |
| LTE Band 2 | | -97.0 | -98.0 | -100.5 | -94.3 |
| LTE Band 3 | | -97.0 | -98.0 | -100.0 | -93.3 |
| LTE Band 4 | | -97.5 | -97.0 | -100.0 | -96.3 |
| LTE Band 5 | | -98.5 | -99.0 | -102.0 | -94.3 |
| LTE Band 7 | | -96.5 | -97.0 | -100.0 | -94.3 |
| LTE Band 8 | | -99.0 | -98.0 | -101.5 | -93.3 |
| LTE Band 12 | | -97.5 | -99.0 | -101.5 | -93.3 |
| LTE Band 13 | | -97.0 | -98.5 | -101.0 | -93.3 |
| LTE Band 20 | | -98.5 | -98.5 | -101.5 | -93.3 |
| LTE Band 25 | | -97.0 | -97.5 | -100.5 | -92.8 |
| LTE Band 26 | | -98.5 | -99.0 | -102.0 | -93.8 |
| LTE Band 29 | | n/a | n/a | -101.75 | -93.3 |
| LTE Band 30 | | -95.5 | -97.0 | -99.5 | -95.3 |
| LTE Band 41 | | -95.5 | -95.5 | -98.5 | -94.3 |

1. Per 3GPP specification
2. Sensitivity values scale with bandwidth:

$$x_MHz_Sensitivity = 10_MHz_Sensitivity - 10 \cdot \log(10 \text{ MHz}/x_MHz)$$
 Note: Bandwidth support is dependent on firmware version.

Table 4-5: Conducted Rx (Receive) Sensitivity—UMTS Bands

| UMTS bands | | Conducted Rx sensitivity (dBm) | | |
|------------|-----------------------|--------------------------------|---------------------|---|
| | | Primary (Typical) | Secondary (Typical) | Primary/Secondary (Worst case) ¹ |
| Band 1 | 0.1% BER 12.2 kbps | -110.5 | -109.0 | -106.0 |
| Band 2 | | -110.0 | -110.0 | -104.0 |
| Band 3 | | -109.5 | -110.0 | -103.0 |
| Band 4 | | -110.0 | -109.5 | -106.0 |
| Band 5 | | -111.0 | -112.0 | -104.0 |
| Band 8 | | -111.5 | -110.5 | -103.0 |

1. Per 3GPP specification

Table 4-6: Conducted Tx (Transmit) Power Tolerances

| Parameter | Conducted transmit power | Notes |
|---|--------------------------|-------------------------|
| LTE | | |
| LTE Band 1,2,3,4,5,8,12,13,20,25,26 | +23 dBm \pm 1 dB | |
| LTE Band 7,30,41 | +22 dBm \pm 1 dB | |
| UMTS | | |
| Band 1 (IMT 2100 12.2 kbps) Band 2 (UMTS 1900 12.2 kbps) Band 3 (UMTS 1800 12.2 kbps) Band 4 (AWS 1700/2100 12.2 kbps) Band 5 (UMTS 850 12.2 kbps) Band 8 (UMTS 900 12.2 kbps) | +23 dBm \pm 1 dB | Connectorized (Class 3) |

GNSS Specifications

Note: For detailed electrical performance criteria, see [Recommended GNSS Antenna Specifications on page 73](#).

Table 4-7: GNSS Specifications

| Parameter/feature | Description |
|--------------------|---|
| Satellite channels | Maximum 30 channels (16 GPS, 14 GLONASS), simultaneous tracking |
| Protocols | NMEA 0183 V3.0 |

Table 4-7: GNSS Specifications (Continued)

| Parameter/feature | Description |
|--------------------|--|
| Acquisition time | Hot start: 1 s Warm start: 29 s Cold start: 32 s <hr style="border: 1px solid red;"/> <i>Note: Measured with signal strength = -135 dBm.</i> <hr style="border: 1px solid red;"/> |
| Accuracy | Horizontal: < 2 m (50%); < 5 m (90%) Altitude: < 4 m (50%); < 8 m (90%) Velocity: < 0.2 m/s |
| Sensitivity | Tracking ¹ : -160 dBm Acquisition ² (Assisted): -158 dBm Acquisition (Standalone): -145 dBm |
| Operational limits | Altitude <6000 m or velocity <100 m/s (Either limit may be exceeded, but not both.) |

1. Tracking sensitivity is the lowest GNSS signal level for which the device can still detect an in-view satellite 50% of the time when in sequential tracking mode.
2. Acquisition sensitivity is the lowest GNSS signal level for which the device can still detect an in-view satellite 50% of the time.

Power Consumption

Power consumption measurements in the tables below are for the MC7455 Mini Card module connected to the host PC via USB.

The module does not have its own power source and depends on the host device for power. For a description of input voltage requirements, see [Power Supply on page 30](#).

Table 5-1: Averaged Standby DC Power Consumption

| Signal | Description | Bands ¹ | Current | | | Notes / configuration | |
|--------|---|--------------------|---------|------------------|------|------------------------|--|
| | | | Typ | Max ² | Unit | | |
| VCC | Standby current consumption (Sleep mode activated³) | | | | | | |
| | LTE | LTE Bands | 3.10 | 3.70 | mA | DRX cycle = 8 (2.56 s) | |
| | DC-HSPA/HSPA / WCDMA | UMTS bands | 3.10 | 3.70 | mA | DRX cycle = 8 (2.56 s) | |
| | Standby current consumption⁴ (Sleep mode deactivated³) | | | | | | |
| | LTE | LTE bands | 35 | 40 | mA | DRX cycle = 8 (2.56 s) | |
| | DC-HSPA/HSPA / WCDMA | UMTS bands | 35 | 40 | mA | DRX cycle = 8 (2.56 s) | |
| | Low Power Mode (LPM)/Offline Mode⁴ (Sleep mode activated³) | | | | | | |
| | RF disabled, but module is operational | | | 2.30 | 3.0 | mA | |
| | Low Power Mode (LPM)/Offline Mode⁴ (Sleep mode deactivated³) | | | | | | |
| | RF disabled, but module is operational | | | 32 | 36 | mA | |
| | Leakage current | | | | | | |
| | Module powered off—W_DISABLE_N is Low, and the module is in OFF state while VCC is supplied | | | 70 | 120 | μA | |

1. For supported bands, see [Table 4-1, LTE Frequency Bands](#), on page 42, and [Table 4-3, WCDMA Frequency Bands](#), on page 43.
2. Measured at 30°C/nominal 3.3 V voltage.
3. Assumes USB bus is fully suspended during measurements
4. LPM and standby power consumption will increase when LEDs are enabled. To reduce power consumption, configure LEDs to remain off while in standby and LPM modes.

Table 5-2: Averaged Call Mode DC Power Consumption

| Description | Tx power | Current ¹ | | Notes |
|-------------------------------------|----------|----------------------|------|----------------------------------|
| | | Typ | Unit | |
| LTE | 0 dBm | 650 | mA | CA 300/50 Mbps, 20 MHz+20 MHz BW |
| | | 350 | mA | CA 100/50 Mbps, 10 MHz+10 MHz BW |
| | | 430 | mA | 150/50 Mbps, 20 MHz BW |
| | 20 dBm | 1000 | mA | CA 300/50 Mbps, 20 MHz+20 MHz BW |
| | | 670 | mA | CA 100/50 Mbps, 10 MHz+10 MHz BW |
| | | 800 | mA | 150/50 Mbps, 20 MHz BW |
| | 23 dBm | 1100 | mA | CA 300/50 Mbps, 20 MHz+20 MHz BW |
| | | 730 | mA | CA 100/50 Mbps, 10 MHz+10 MHz BW |
| | | 870 | mA | 150/50 Mbps, 20 MHz BW |
| DC-HSPA/HSPA / WCDMA | 0 dBm | 320 | mA | All speeds |
| | 20 dBm | 450 | mA | All speeds |
| | 23 dBm | 600 | mA | Worst case |
| Peak current (averaged over 100 μs) | | 2.24 | A | All LTE/WCDMA bands |

1. Measured at 30°C/nominal 3.3 V voltage

Table 5-3: Miscellaneous DC Power Consumption

| Signal | Description | Current/Voltage | | | Unit | Notes / configuration |
|-----------------------|--------------------------|-----------------|------|------|------|---|
| | | Min | Typ | Max | | |
| VCC | USB active current | — | 15 | 20 | mA | High speed USB connection, C _L = 50 pF on D+ and D- signals |
| | Inrush current | — | 2.2 | 2.5 | A | <ul style="list-style-type: none"> Assumes power supply turn on time > 100μs Dependent on host power supply rise time. |
| | Maximum current | — | — | 1.5 | A | <ul style="list-style-type: none"> Across all bands, all temperature ranges 3.3 V supply |
| GNSS Signal connector | Active bias on GNSS port | — | — | 100 | mA | GNSS RF connector in Figure 4-1 on page 37 |
| | | 3.05 | 3.15 | 3.25 | V | |

Module Power States

The module has four power states, as described in [Table 5-4](#).

Table 5-4: Module Power States

| State | Details | Host is powered | Module is powered | USB interface active | RF enabled |
|------------------------------------|--|-----------------|-------------------|----------------------|------------|
| Normal (Default state) | <ul style="list-style-type: none"> Module is active Default state when VCC is first applied in the absence of W_DISABLE_N control Module is capable of placing/receiving calls, or establishing data connections on the wireless network Current consumption is affected by several factors, including: <ul style="list-style-type: none"> Radio band being used Transmit power Receive gain settings Data rate Number of active Tx time slots | ✓ | ✓ | ✓ | ✓ |
| Low power ('Airplane mode') | <ul style="list-style-type: none"> Module is active Module enters this state: <ul style="list-style-type: none"> Under host interface control: <ul style="list-style-type: none"> Host issues AT+CFUN=0 ([1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)), or Host issues AT!PCOFFEN=0 (configures the modem to enter low power mode when W_DISABLE_N is asserted), and then asserts W_DISABLE_N Automatically, when critical temperature or voltage trigger limits have been reached | ✓ | ✓ | ✓ | ✗ |
| Sleep | <ul style="list-style-type: none"> Normal state of module between calls or data connections Module cycles between wake (polling the network) and sleep, at network provider-determined interval. | ✓ | ✓ | ✗ | ✗ |
| Disconnected | <ul style="list-style-type: none"> Host power source is disconnected from the module and all voltages associated with the module are at 0 V. | ✗ | ✗ | ✗ | ✗ |

Power State Transitions

The module uses state machines to monitor supply voltage and operating temperature, and notifies the host when critical threshold limits are exceeded. (See [Table 5-5](#) for trigger details and [Figure 5-1](#) for state machine behavior.)

Power state transitions may occur:

- Automatically, when critical supply voltage or module temperature trigger levels are encountered.
- Under host control, using available AT commands in response to user choices (for example, opting to switch to airplane mode) or operating conditions.

Table 5-5: Power State Transition Trigger Levels

| Transition | Voltage | | Temperature ¹ | | Notes |
|--|--------------|----------------|--------------------------|-----|--|
| | Trigger | v ² | Trigger | °C | |
| Normal to Low Power | VOLT_HI_CRIT | 3.8 | TEMP_LO_CRIT | -45 | • RF activity suspended |
| | VOLT_LO_CRIT | 2.9 | TEMP_HI_CRIT | 93 | |
| Low Power to Normal | VOLT_HI_NORM | 3.5 | TEMP_NORM_LO | -30 | • RF activity resumed |
| Low Power to Normal or Remain in Normal (Remove warnings) | VOLT_LO_NORM | 3.05 | TEMP_HI_NORM | 70 | |
| Normal (Issue warning) | VOLT_LO_WARN | 2.95 | TEMP_HI_WARN | 80 | • In the TEMP_HI_WARN state, the module may have reduced performance (Class B temp. range). |
| Power off/on (Host-initiated) | - | - | - | - | • Power off recommended when supply voltage or module operating temperature is critically low or high. |

1. Module-reported temperatures at the printed circuit board.
2. Supply voltage—3.3V

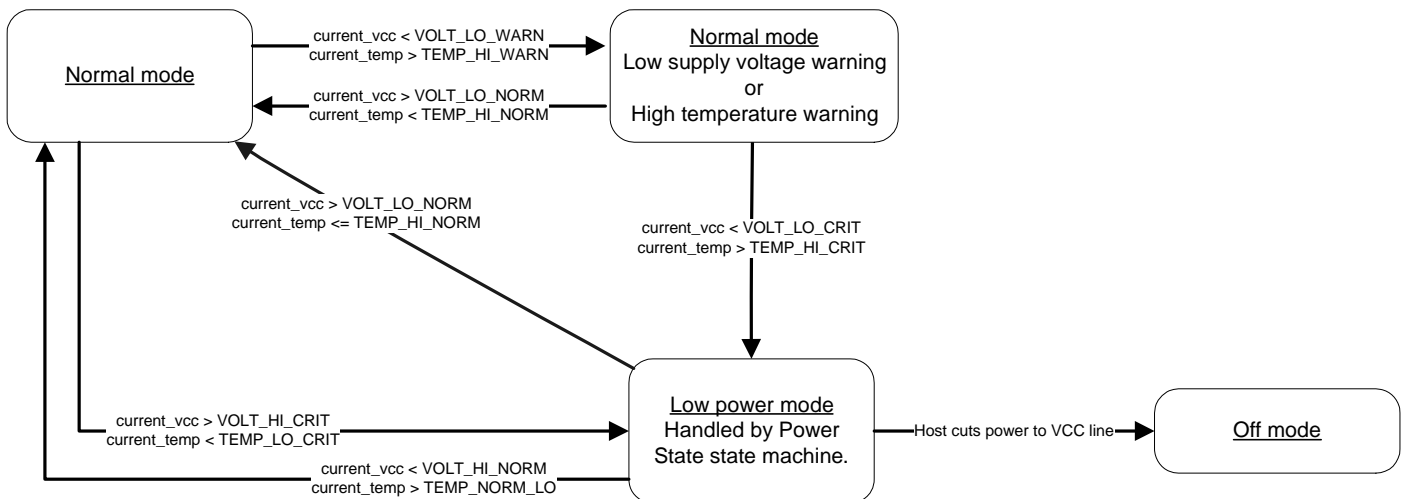


Figure 5-1: Voltage/Temperature Monitoring State Machines

Power Interface

Power Ramp-up

On initial power up, inrush current depends on the power supply rise time—turn on time >100 μ s is required for < 3A inrush current.

The supply voltage must remain within specified tolerances while this is occurring.

Power-On/Off Timing

Figure 5-2 describes the timing sequence for powering the module on and off.

Note: The host should not drive any signals to the module until the power-on sequence is complete.

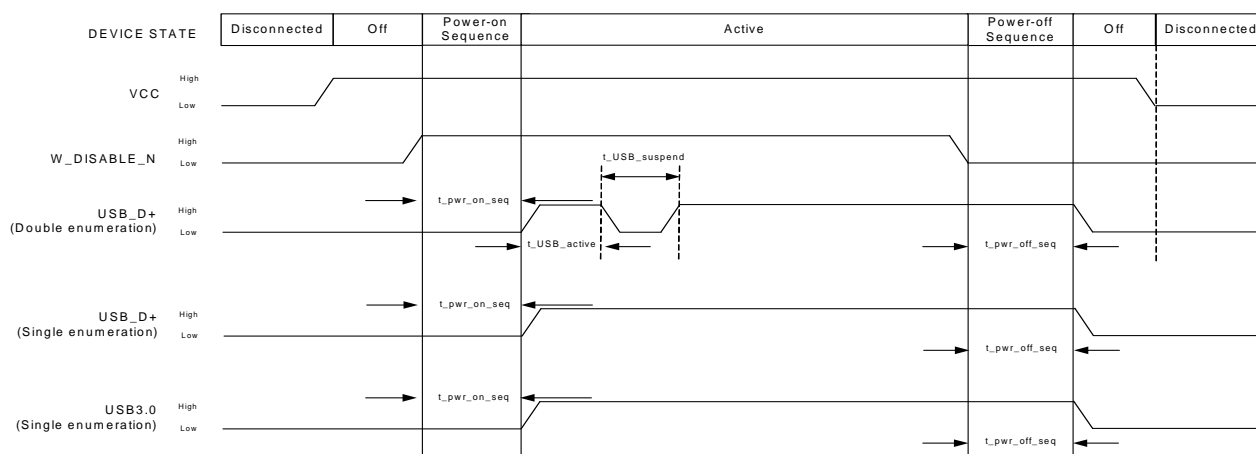


Figure 5-2: Signal Timing ($W_DISABLE_N$, and USB Enumeration)

Table 5-6: USB 2.0 Power-On/Off Timing Parameters (Double Enumeration)

| Parameter | Typical (s) | Maximum (s) |
|----------------------|-------------|-------------|
| t_pwr_on_seq | 0.55 | 0.65 |
| t_USB_active | 0.15 | 0.2 |
| t_USB_suspend | 7.5 | 11 |
| t_pwr_off_seq | 20 | 25 |

Table 5-7: USB 2.0 Power-On/Off Timing Parameters (Single Enumeration)

| Parameter | Typical (s) | Maximum (s) |
|---------------|-------------|-------------|
| t_pwr_on_seq | 8.6 | 11 |
| t_pwr_off_seq | 20 | 25 |

Table 5-8: USB 3.0 Power-On/Off Timing Parameters (Single Enumeration)

| Parameter | Typical (s) | Maximum (s) |
|---------------|-------------|-------------|
| t_pwr_on_seq | 8.5 | 11 |
| t_pwr_off_seq | 20 | 25 |

USB Enumeration

The unit supports single and double USB enumeration with the host:

- Single enumeration:
 - Applies to USB 2.0 and USB 3.0
 - Enumeration starts within maximum t_pwr_on_seq seconds of power-on.
- Double enumeration—As shown in [Figure 5-2](#) on page 51:
 - Applies to USB 2.0 only
 - First enumeration starts within t_pwr_on_seq seconds of power-on (while USB_D+ is high)
 - Second enumeration starts after t_USB_suspend (when USB_D+ goes high again)

Power Supply Noise

Noise in the power supply can lead to noise in the RF signal.

The power supply ripple limit for the module is no more than 100 mVp-p 1 Hz to 100 kHz. This limit includes voltage ripple due to transmitter burst activity.

Additional decoupling capacitors can be added to the main VCC line to filter noise into the device.

SED (Smart Error Detection)

The module uses a form of SED to track premature modem resets.

- Module tracks consecutive resets occurring soon after power-on.
- After a sixth consecutive reset, the module waits in boot-and-hold mode for a firmware download to resolve the power-cycle problem.

Tx Power Control

The module's Tx power limit may be controlled using either SAR backoff AT commands (defined in [2] *AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*), or the DPR (Dynamic power control) signal. Use the GPIOARENABLE parameter for !CUSTOM to choose the method:

- AT commands:
 - !SARSTATED—Set (or report) the default SAR backoff state that the device uses when it powers up. This setting persists across power cycles and overrides any PRI setting.
 - !SARSTATE—Set (or report) the current SAR backoff state (override the default state). This change in state is non-persistent across power cycles.
 - !SARBACKOFF—Set (or report) the maximum Tx power limit for a specific band/technology/state combination.
- Dynamic power control—The module's firmware monitors DPR (pin 46) and adjusts the RF Tx power appropriately, as detailed in [Table 5-9 on page 53](#). (This state change is equivalent to using the !SARSTATE AT command.)

Note: A customization is available to invert the DPR logic. (e.g. DPR low = No SAR backoff)

Table 5-9: Dynamic Power Control of SAR Backoff State

| DPR | SAR backoff state |
|-------------------|-------------------|
| High ¹ | No SAR backoff |
| Low | Backoff 1 |

1. DPR is pulled high by default.

Note: The host can implement an open collector drive for the DPR pin (if a 1.8 V-compatible drive is not available.)

6: Software Interface

Support Tools

The MC7455 is compatible with the following support tools from Sierra Wireless and authorized third parties:

- Firmware update utilities from Sierra Wireless
- Sierra Wireless Logger
- QXDM from QUALCOMM
- QUALCOMM Product Support Tool (QPST)
- Windows and Linux SDKs (including API and drivers)

USB Interface

The device supports the following protocols for modem communication:

- Qualcomm QMI interface. (Please contact your Sierra Wireless account representative for QMI interface documentation.)
- MBIM (Mobile Broadband Interface Model)

MTU Size (Windows 7)

The MTU (Maximum Transmission Unit) size is configured using a driver installer command line option:

MTUSize=<value> (<value> is the size in bytes)

Example:

```
driverinstaller /MTUSize=1428
```

Note: Wireless network operators will have their own specific MTU requirements.

7: Mechanical and Environmental Specifications

The MC7455 module complies with the mechanical and environmental specifications in [Table 7-1](#). Final product conformance to these specifications depends on the [OEM](#) device implementation.

Table 7-1: Mechanical and Environmental Specifications

| | Mode | Details |
|--|---------------------|--|
| Ambient temperature | Operational Class A | -30°C to +70°C – 3GPP compliant |
| | Operational Class B | -40°C to +85°C – non-3GPP compliant (reduced operating parameters required) |
| | Non-operational | -40°C to +85°C, 96 hours (from MIL-STD 202 Method 108) |
| Relative humidity | Non-operational | 85°C, 85% relative humidity for 48 hours (non-condensing) |
| Vibration | Non-operational | Random vibration, 10 to 2000 Hz, 0.1 g ² /Hz to 0.0005 g ² /Hz, in each of three mutually perpendicular axes. Test duration of 60 minutes for each axis, for a total test time of three hours. |
| Shock | Non-operational | Half sine shock, 11 ms, 30 g, 8x each axis. Half sine shock, 6 ms, 100 g, 3x each axis. |
| Drop | Non-operational | 1 m on concrete on each of six faces, two times (module only). |
| (Electrostatic discharge (See Electrostatic Discharge (ESD) on page 59.) | Operational | The RF port (antenna launch and RF connector) complies with the IEC 61000-4-2 standard: <ul style="list-style-type: none"> Electrostatic Discharge Immunity: Test: Level3 Contact Discharge: ±6 kV Air Discharge: ±8 kV |
| | Non-operational | The host connector Interface complies with the following standard only: <ul style="list-style-type: none"> minimum ±500 V Human Body Model (JESD22-A114-B) |
| Thermal considerations | | See Thermal Considerations on page 60. |
| Form factor | | PCI-Express Mini Card shielded with metal and metalized fabric (F2 specification) |
| Dimensions | | Length: 50.95 mm Width: 30 mm Thickness: 2.75 mm (max) Weight: 8.7 g |

Device Views

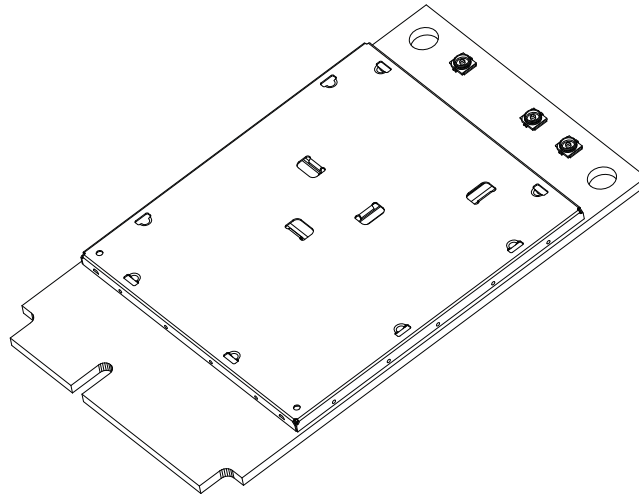


Figure 7-1: Top View

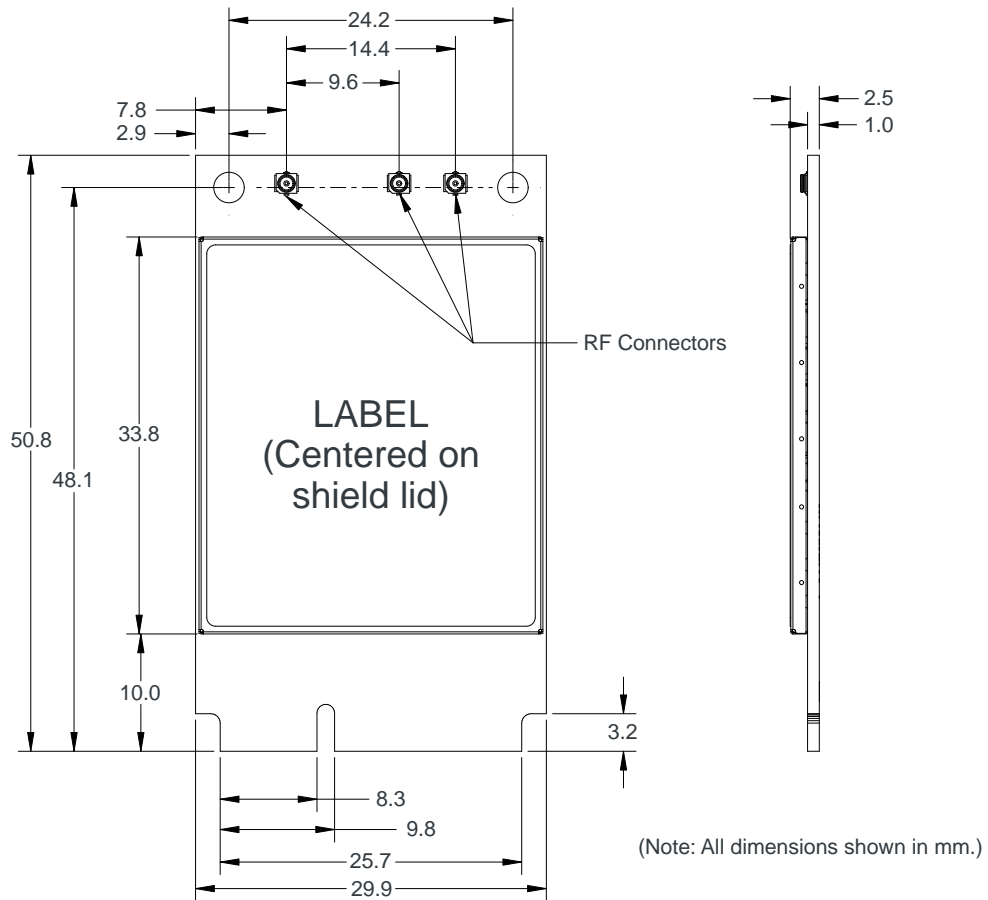


Figure 7-2: Dimensioned View

Labeling

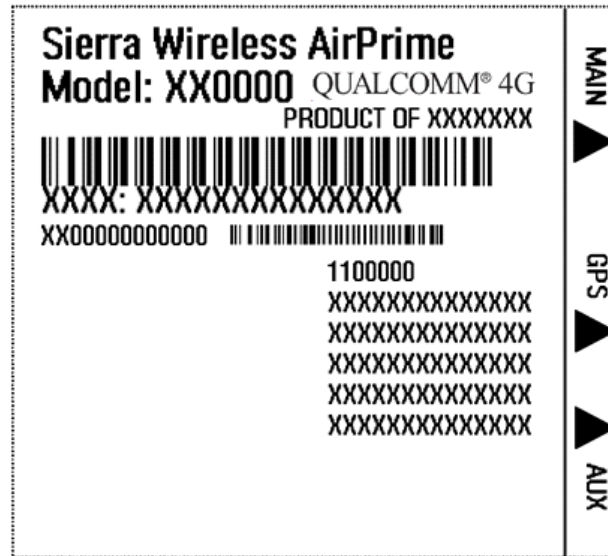


Figure 7-3: Sample Unit Label

Note: The displayed label is an example only. The production label will vary by [SKU](#).

The MC7455 label is non-removable and contains:

- Sierra Wireless logo and product name
- [IMEI](#) number in Code-128 barcode format
- [SKU](#) number (when required)
- Factory Serial Number ([FSN](#)) in alphanumeric format
- Manufacturing date code (incorporated into FSN)
- Licensed vendor logo
- Applicable certification marks/details (e.g. FCC ID, CE information, etc. Example shows FCC ID.)

Note: The MC7455 supports [OEM](#) partner-specific label requirements.

Electrostatic Discharge (ESD)

The OEM is responsible for ensuring that the Mini Card host interface pins are not exposed to ESD during handling or normal operation. (See [Table 7-1 on page 57](#) for specifications.)

ESD protection is highly recommended for the SIM connector at the point where the contacts are exposed, and for any other signals from the host interface that would be subjected to ESD by the user of the product. (The device includes ESD protection on the antenna.)

Thermal Considerations

Embedded modules can generate significant amounts of heat that must be dissipated in the host device for safety and performance reasons.

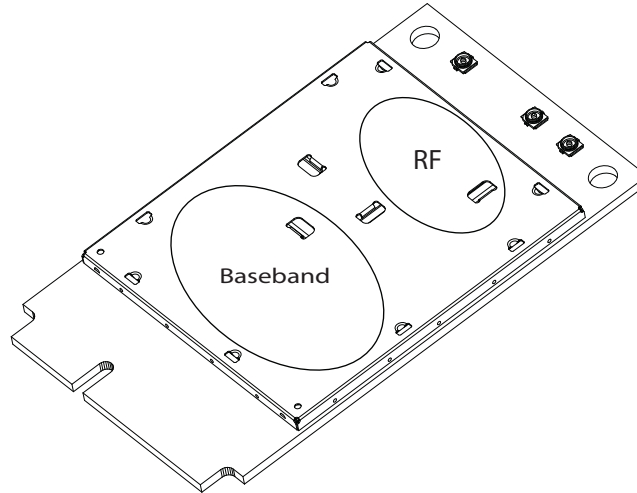


Figure 7-4: Shield locations (Top view)

The amount of thermal dissipation required depends on:

- Supply voltage—Maximum power dissipation for the module can be up to 3.5 W at voltage supply limits.
- Usage—Typical power dissipation values depend on the location within the host product, throughput, amount of data transferred, etc.

Specific areas requiring heat dissipation are shown in [Figure 7-4](#):

- RF—Bottom face of module near RF connectors. Likely to be the hottest area.
- Baseband—Bottom face of module, below the baseband area.

To enhance heat dissipation:

- It is recommended to add a heat sink that mounts the module to the main PCB or metal chassis (a thermal compound or pads must be used between the module and the heat sink).

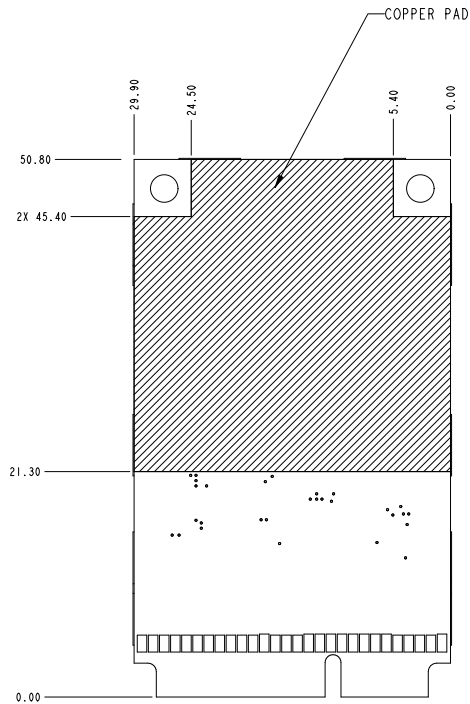


Figure 7-5: Copper Pad Location on Bottom Side of Module

- Maximize airflow over/around the module.
- Locate the module away from other hot components.
- Module mounting holes must be used to attach (ground) the device to the main PCB ground or a metal chassis.
- You may also need active cooling to pull heat away from the module.

Note: Adequate dissipation of heat is necessary to ensure that the module functions properly.

Module Integration Testing

When testing your integration design:

- Test to your worst case operating environment conditions (temperature and voltage)
- Test using worst case operation (transmitter on 100% duty cycle, maximum power)
- Monitor temperature on the underside of the module. Attach thermocouples to the areas indicated in [Figure 7-4](#) on page 60 (Baseband, RF).
- Monitor the module's internal temperature using the command **AT!PCTEMP**. (See [2] *AirPrime EM74xx/MC74xx AT Command Reference* (Doc# 4117727).)

Note: Make sure that your system design provides sufficient cooling for the module—proper mounting, heat sinks, and active cooling may be required, depending on the integrated application.

The internal module temperature (reported by AT!PCTEMP) must be kept to <90°C when integrated to prevent damage to the module's components. For best performance, keep the internal module temperature below 80°C.

(For acceptance, certification, quality, and production (including RF) test suggestions, see [Testing on page 77.](#))

8: Regulatory Compliance and Industry Certifications

This module is designed to meet, and upon commercial release, will meet the requirements of the following regulatory bodies and regulations, where applicable:

- Federal Communications Commission (FCC) of the United States
- The Certification and Engineering Bureau of Industry Canada (IC)
- The National Communications Commission (NCC) of Taiwan, Republic of China
- Radio Equipment and Telecommunications Terminal Equipment (R&TTE) Directive of the European Union

Upon commercial release, the following industry certifications will have been obtained, where applicable:

- GCF
- PTCRB

Additional certifications and details on specific country approvals may be obtained upon customer request—contact your Sierra Wireless account representative for details.

Additional testing and certification may be required for the end product with an embedded MC7455 module and are the responsibility of the [OEM](#). Sierra Wireless offers professional services-based assistance to OEMs with the testing and certification process, if required.

Important Notice

Because of the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless module are used in a normal manner with a well-constructed network, the Sierra Wireless module should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless and its affiliates accept no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless module, or for failure of the Sierra Wireless module to transmit or receive such data.

Safety and Hazards

Do not operate your MC7455 module:

- In areas where blasting is in progress
- Where explosive atmospheres may be present including refuelling points, fuel depots, and chemical plants
- Near medical equipment, life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the MC7455 module **MUST BE POWERED OFF**. Otherwise, the MC7455 module can transmit signals that could interfere with this equipment.

In an aircraft, the MC7455 module **MUST BE POWERED OFF**. Otherwise, the MC7455 module can transmit signals that could interfere with various onboard systems and may be dangerous to the operation of the aircraft or disrupt the cellular network. Use of a cellular phone in an aircraft is illegal in some jurisdictions. Failure to observe this instruction may lead to suspension or denial of cellular telephone services to the offender, or legal action or both.

Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. The MC7455 module may be used normally at this time.

Important Compliance Information for North American Users

Note: Details are preliminary and subject to change.

The MC7455 module, upon commercial release, will have been granted modular approval for mobile applications. Integrators may use the MC7455 module in their final products without additional FCC/IC (Industry Canada) certification if they meet the following conditions. Otherwise, additional FCC/IC approvals must be obtained.

1. At least 20 cm separation distance between the antenna and the user's body must be maintained at all times.
2. To comply with FCC / IC regulations limiting both maximum RF output power and human exposure to RF radiation, the maximum antenna gain including cable loss in a mobile-only exposure condition must not exceed the limits stipulated in [Table 8-1 on page 65](#).

Table 8-1: Antenna Gain Specifications

| Device | Technology | Band | Frequency (MHz) | Maximum antenna gain (dBi) |
|------------------|------------|------|-----------------|----------------------------|
| MC7455 Mini Card | LTE | 2 | 1850–1910 | 6 |
| | | 4 | 1710–1755 | 6 |
| | | 5 | 824–849 | 6 |
| | | 7 | 2500–2570 | 9 |
| | | 12 | 699–716 | 6 |
| | | 13 | 777–787 | 6 |
| | | 25 | 1850–1915 | 6 |
| | | 26 | 814–849 | 6 |
| | | 30 | 2305–2315 | 1 (See note below.) |
| | | 41 | 2496–2690 | 9 |
| | UMTS | 2 | 1850–1910 | 6 |
| | | 4 | 1710–1755 | 6 |
| | | 5 | 824–849 | 6 |

Important: The FCC and IC have a strict EIRP limit in Band 30 for mobile and portable stations in order to protect adjacent satellite radio, aeronautical mobile telemetry, and deep space network operations. Mobile and portable stations must not have antenna gain exceeding 1 dBi in Band 30. Additionally, both the FCC and IC prohibit the use of external vehicle-mounted antennas for mobile and portable stations in this band.

Fixed stations may use antennas with higher gain in Band 30 due to relaxed EIRP limits. EM7455 modules used as fixed subscriber stations in Canada or fixed customer premises equipment (CPE) stations in the United States may have an antenna gain up to 10 dBi in Band 30, however, the use of outdoor antennas or outdoor station installations are prohibited except if professionally installed in locations that are at least 20 meters from roadways or in locations where it can be shown that the ground power level of -44 dBm per 5 MHz in the bands 2305–2315 MHz and 2350–2360 MHz or -55 dBm per 5 MHz in the bands 2315–2320 MHz and 2345–2350 MHz will not be exceeded at the nearest roadway. For the purposes of this notice, a roadway includes a highway, street, avenue, parkway, driveway, square, place, bridge, viaduct or trestle, any part of which is intended for use by the general public for the passage of vehicles.

Mobile carriers often have limits on total radiated power (TRP), which requires an efficient antenna. The end product with an embedded module must output sufficient power to meet the TRP requirement but not too much to exceed FCC / IC's EIRP limit. If you need assistance in meeting this requirement, please contact Sierra Wireless.

3. The MC7455 module may transmit simultaneously with other collocated radio transmitters within a host device, provided the following conditions are met:
 - Each collocated radio transmitter has been certified by FCC/IC for mobile application.
 - At least 20 cm separation distance between the antennas of the collocated transmitters and the user’s body must be maintained at all times.
 - The output power and antenna gain in a collocated configuration must not exceed the limits and configurations stipulated in [Table 8-2](#).

Table 8-2: Collocated Radio Transmitter Specifications

| Device | Technology | Frequency (MHz) | EIRP Limit (dBm) |
|--------------------------------------|------------|-----------------|------------------|
| Collocated transmitters ¹ | WLAN | 2400–2500 | 25 |
| | | 5150–5850 | 27 |
| | WiMAX | 2300–2400 | 25 |
| | | 2500–2700 | 25 |
| | | 3300–3800 | 25 |
| | BT | 2400–2500 | 15 |

1. Valid collocated transmitter combinations: WLAN+BT; WiMAX+BT. (WLAN+WiMAX+BT is not permitted.)

4. A label must be affixed to the outside of the end product into which the MC7455 module is incorporated, with a statement similar to the following:
 - **This device contains FCC ID: N7NMC7455.**
Contains transmitter module IC: 2417C-MC7455 where 2417C-MC73542417C-MC7355 is the module’s certification number.
5. A user manual with the end product must clearly indicate the operating requirements and conditions that must be observed to ensure compliance with current FCC / IC RF exposure guidelines.

The end product with an embedded MC7455 module may also need to pass the FCC Part 15 unintentional emission testing requirements and be properly authorized per FCC Part 15.

Note: If this module is intended for use in a portable device, you are responsible for separate approval to satisfy the SAR requirements of FCC Part 2.1093 and IC RSS-102.

➤➤ A: Audio Support



The MC7455 host I/O connector provides pins to support PCM or I2S audio interfaces as listed in Table A-1.

Table A-1: Connector Pin Assignments^a

| Pin | Signal name | Pin type ^b | Description | Direction to module | Active state | Voltage levels (V) | | |
|-----|----------------------------------|-----------------------|---|---------------------|--------------|--------------------|------|------|
| | | | | | | Min | Typ | Max |
| 30 | I2C_CLK ^c | - | I2C serial bus clock | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| | | | | Output Low | | 0.00 | | 0.45 |
| 32 | I2C_DATA ^c | - | I2C serial bus data | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.3 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| | | | | Output Low | | 0.00 | | 0.45 |
| 45 | PCM_CLK / I2S_CLK ^d | - | (PCM_CLK) PCM Clock—Input in Slave mode, output in Master mode | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| | | | | Output Low | | 0.00 | | 0.45 |
| | | | (I2S_CLK) I ² S Clock | Output | High | 1.35 | - | 1.90 |
| | | | | Output | Low | 0 | - | 0.45 |
| 47 | PCM_DOUT / I2S_DOUT ^d | - | PCM Data Out / I ² S Data Out | Output | High | 1.35 | 1.80 | 1.90 |
| | | | | Output | Low | 0 | | 0.45 |
| 49 | PCM_DIN / I2S_DIN ^d | - | PCM Data In / I ² S Data In | Input | High | 1.17 | 1.80 | 2.10 |
| | | | | Input | Low | -0.30 | | 0.63 |
| 51 | PCM_WS / I2S_SYNC ^d | - | PCM Sync—Input in Slave mode, output in Master mode | Input High | | 1.17 | 1.80 | 2.10 |
| | | | | Input Low | | -0.30 | | 0.63 |
| | | | | Output High | | 1.35 | 1.80 | 1.90 |
| | | | | Output Low | | 0.00 | | 0.45 |
| | | | I ² S WS | Output | High | 1.35 | - | 1.90 |
| | | | | Output | Low | 0 | - | 0.45 |

- a. The host should leave all 'NC' ('no connect) pins unconnected.
- b. A—Analog; I—Input; NP—No pull; O—Digital output; OC—Open Collector; PU—Digital input (internal pull up); PD—Digital output (internal pull down); V—Power or ground
- c. Leave both I2C pins as No Connect if I2C interface is not used.
- d. PCM Master/Slave mode and I2S Master mode are supported.

PCM/I2S Audio Interface

The module implements a PCM/I²S digital audio interface using a dedicated serial link for digital audio data; all other signals, such as subcoding and control, are transmitted separately. Default setting is PCM slave mode, but this can be switched, using AT commands, to PCM master mode, I²S master mode, or I²S slave mode.

PCM/I²S signals are summarized in the following table.

Table A-2: PCM/I²S Interface Signals

| Signal name | Pin | Description |
|-------------------|-----|---------------------------|
| PCM_CLK/I2S_CLK | 45 | PCM Clock/I2S Clock |
| PCM_DOUT/I2S_DOUT | 47 | PCM Data Out/I2S Data Out |
| PCM_DIN/I2S_DIN | 49 | PCM Data In/I2S Data In |
| PCM_SYNC/I2S_WS | 51 | PCM Sync/I2S Word Select |

PCM

The PCM interface supports the following features:

- Modes: Master and slave
- Auxiliary PCM This is in EM, is it in mc as well?
- Sampling rates: 8 kHz, 16 kHz
- Audio compression formats: Linear, μ -law, A-Law
- Padding: Disabled, enabled
- Bits per frame: 8, 16, 32, 64, 128, 256
- Bit frequency: (Sampling rate * Bits per frame)

The following figures and table illustrate PCM signals timing.

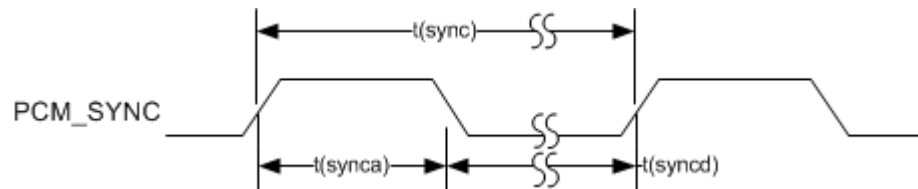


Figure A-1: Timing—PCM_SYNC

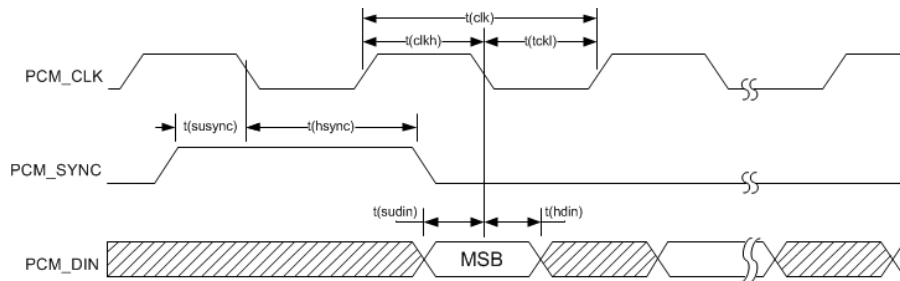


Figure A-2: Timing—PCM Codec to Module

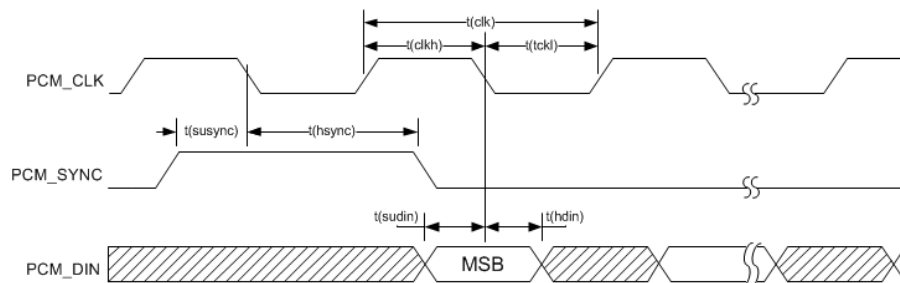


Figure A-3: Timing—Module to PCM Codec

Table A-3: PCM Timing^a

| Parameter | Description | Min | Typ | Max | Units |
|-----------------------|---|-----|-------|-----|-------|
| T(sync) | PCM_FS cycle time | - | 125 | - | us |
| T(synch) | PCM_FS high time | - | 488 | - | ns |
| T(cyncl) | PCM_FS low time | - | 124.5 | - | us |
| T(clk) | PCM_CLK cycle time | - | 488 | - | ns |
| T(clkh) | PCM_CLK high time | - | 244 | - | ns |
| T(clkl) | PCM_CLK low time | - | 244 | - | ns |
| T(sync_offset) | PCM_SYNC offset time to PCM_CLK falling | - | 122 | - | ns |
| T(sudin) | PCM_DIN setup time before falling edge of PCM_CLK | 60 | - | - | ns |
| T(hdin) | PCM_DIN hold time after falling edge of PCM_CLK | 60 | - | - | ns |
| T(pdout) | Delay from PCM_CLK rising to PCM_DOUT valid | - | - | 60 | ns |
| T(zdout) | Delay from PCM_CLK falling to PCM_DOUT HIGH-Z | - | - | 60 | ns |

a. Maximum PCM clock rate is 2.048 MHz.

I²S

The I²S interface can be used to transfer serial digital audio to or from an external stereo DAC/ADC and supports the following features:

- Modes: Master (Slave mode is not supported)
- Sampling rates: 48 kHz
- Bits per frame: 16
- Bit clock: 1536 kHz

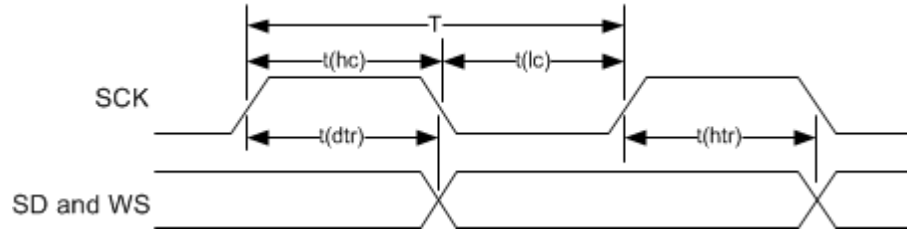


Figure A-4: I2S Transmitter Timing

Table A-4: Master Transmitter with Data Rate = 1.536 MHz (±10%)^a

| Parameter | Description | Condition | Min | Typ | Max | Units |
|---------------|--------------|------------------------------|-----|-----|-----|-------|
| T | Clock period | I2S requirement: min T=293 | 293 | 326 | 359 | ns |
| t(hc) | Clock high | I2S requirement: min > 0.35T | 120 | - | - | ns |
| t(lc) | Clock low | I2S requirement: min > 0.35T | 120 | - | - | ns |
| t(dtr) | Delay | I2S requirement: max < 0.8T | - | - | 250 | ns |
| t(htr) | Hold time | I2S requirement: min > 0 | 100 | - | - | ns |

a. Maximum sample rate = 48 KHz at 1.536 MHz (16 bits per sample)

»» B: Antenna Specification

This appendix describes recommended electrical performance criteria for main path, diversity path, and GNSS antennas used with AirPrime embedded modules.

The performance specifications described in this section are valid while antennas are mounted in the host device with antenna feed cables routed in their final application configuration.

*Note: Antennas should be designed **before** the industrial design is finished to make sure that the best antennas can be developed.*

Recommended Main/Diversity Antenna Specifications

Table B-1: Antenna Requirements ^a

| Parameter | Requirements | Comments |
|------------------------------------|---|---|
| Antenna system | (LTE) External multi-band 2x2 MIMO antenna system (Ant1/Ant2) ^b (3G) External multi-band antenna system with diversity (Ant1/Ant2) ^c | If Ant2 includes GNSS, then it must also satisfy requirements in Table B-2 on page 73 . |
| Operating bands — Antenna 1 | 669–960 MHz | |
| | 1710–1995 MHz | |
| | 2110–2170 MHz | |
| | 2300–2690 MHz | |
| Operating bands — Antenna 2 | 717–960 MHz | |
| | 1805–1995 MHz | |
| | 2110–2170 MHz | |
| | 2350–2690 MHz | |
| VSWR of Ant1 and Ant2 | <ul style="list-style-type: none"> < 2:1 (recommended) < 3:1 (worst case) | On all bands including band edges |

Table B-1: Antenna Requirements (Continued)^a

| Parameter | Requirements | Comments |
|--|--|--|
| Total radiated efficiency of Ant1 and Ant2 | > 50% on all bands | <ul style="list-style-type: none"> Measured at the RF connector. Includes mismatch losses, losses in the matching circuit, and antenna losses, excluding cable loss. Sierra Wireless recommends using antenna efficiency as the primary parameter for evaluating the antenna system. Peak gain is not a good indication of antenna performance when integrated with a host device (the antenna does not provide omni-directional gain patterns). Peak gain can be affected by antenna size, location, design type, etc.—the antenna gain patterns remain fixed unless one or more of these parameters change. |
| Radiation patterns of Ant1 and Ant2 | Nominally Omni-directional radiation pattern in azimuth plane. | |
| Envelope correlation coefficient between Ant1 and Ant2 | <ul style="list-style-type: none"> < 0.4 on low Rx bands (up to 1500 MHz) < 0.2 on high Rx bands (over 1500 MHz) | |
| Mean Effective Gain of Ant1 and Ant2 (MEG1, MEG2) | ≥ -3 dBi | |
| Ant1 and Ant2 Mean Effective Gain Imbalance I MEG1 / MEG2 I | < 2 dB for MIMO operation < 6 dB for diversity operation | |
| Maximum antenna gain | Must not exceed antenna gains due to RF exposure and ERP/ EIRP limits, as listed in the module's FCC grant. | See Important Compliance Information for North American Users on page 64 . |

Table B-1: Antenna Requirements (Continued)^a

| Parameter | Requirements | Comments |
|--|--|---|
| Isolation between Ant1 and Ant2 (S21) | > 10 dB | <ul style="list-style-type: none"> If antennas can be moved, test all positions for both antennas. Make sure all other wireless devices (Bluetooth or WLAN antennas, etc.) are turned OFF to avoid interference. |
| Power handling | <ul style="list-style-type: none"> > 2 W RF power on low bands > 1 W on high bands | <ul style="list-style-type: none"> Measure power endurance over 4 hours (estimated talk time) using a 2 W CW signal—set the CW test signal frequency to the middle of the PCS Tx band (1880 MHz for PCS). Visually inspect device to ensure there is no damage to the antenna structure and matching components. VSWR/TIS/TRP measurements taken before and after this test must show similar results. |

- a. These worst-case VSWR figures for the transmitter bands may not guarantee RSE levels to be within regulatory limits. The device alone meets all regulatory emissions limits when tested into a cabled (conducted) 50 ohm system. With antenna designs with up to 2.5:1 VSWR or worse, the radiated emissions could exceed limits. The antenna system may need to be tuned in order to meet the RSE limits as the complex match between the module and antenna can cause unwanted levels of emissions. Tuning may include antenna pattern changes, phase/delay adjustment, passive component matching. Examples of the application test limits would be included in FCC Part 22, Part 24 and Part 27, test case 4.2.2 for WCDMA (ETSI EN 301 908-1), where applicable.
- b. Ant1—Primary, Ant2—Secondary (Diversity/MIMO/GNSS)
- c. Ant1—Primary, Ant2—Secondary (Diversity/GNSS)

Recommended GNSS Antenna Specifications

Table B-2: GNSS Antenna Requirements

| Parameter | Requirements | Comments |
|----------------------------|---|----------|
| Frequency range | <ul style="list-style-type: none"> Wide-band GNSS: 1560–1606 MHz recommended Narrow-band GPS: 1575.42 MHz \pm2 MHz minimum Narrow-band Galileo: 1575.42 MHz \pm2 MHz minimum Narrow-band BeiDou: 1561.098 MHz \pm2 MHz minimum Narrow-band GLONASS: 1601.72 MHz \pm4.2 MHz minimum | |
| Field of view (FOV) | <ul style="list-style-type: none"> Omni-directional in azimuth -45° to +90° in elevation | |

Table B-2: GNSS Antenna Requirements (Continued)

| Parameter | Requirements | Comments |
|---|--|---|
| Polarization (average Gv/Gh) | > 0 dBi | Vertical linear polarization is sufficient. |
| Free space average gain (Gv+Gh) over FOV | > -6 dBi (preferably > -3 dBi) | Gv and Gh are measured and averaged over -45° to +90° in elevation, and ±180° in azimuth. |
| Gain | <ul style="list-style-type: none"> Maximum gain and uniform coverage in the high elevation angle and zenith. Gain in azimuth plane is not desired. | |
| Average 3D gain | > -5 dBi | |
| Isolation between GNSS and Ant1 | > 10 dB in all uplink bands | |
| Typical VSWR | < 2.5:1 | |
| Polarization | Any other than LHCP (left-hand circular polarized) is acceptable. | |

Antenna Tests

The following guidelines apply to the requirements described in [Table B-1 on page 71](#) and [Table B-2 on page 73](#):

- Perform electrical measurements at room temperature (+20°C to +26°C) unless otherwise specified
- For main and diversity path antennas, make sure the antennas (including contact device, coaxial cable, connectors, and matching circuit with no more than six components, if required) have nominal impedances of 50 Ω across supported frequency bands.
- All tests (except isolation/correlation coefficient)—Test the main or diversity antenna with the other antenna terminated.
- Any metallic part of the antenna system that is exposed to the outside environment needs to meet the electrostatic discharge tests per IEC61000-4-2 (conducted discharge +8kV).
- The functional requirements of the antenna system are tested and verified while the embedded module’s antenna is integrated in the host device.

Note: Additional testing, including active performance tests, mechanical, and accelerated life tests can be discussed with Sierra Wireless’ engineering services. Contact your Sierra Wireless representative for assistance.

»» C: Design Checklist

This chapter provides a summary of the design considerations mentioned throughout this guide. This includes items relating to the power interface, RF integration, thermal considerations, cabling issues, and so on.

Note: This is NOT an exhaustive list of design considerations. It is expected that you will employ good design practices and engineering principles in your integration.

Table C-1: Hardware Integration Design Considerations

| Suggestion | Section where discussed |
|---|--|
| Component placement | |
| Protect the SIM socket so the SIM cannot be removed while the host is powered up. | SIM Implementation on page 33 |
| If an ESD suppressor is not used, allow space on the SIM connector for series resistors in layout. (Up to 100 Ω may be used depending on ESD testing requirements). | SIM Implementation on page 33 |
| Minimize RF cable losses as these affect performance values listed in product specification documents. | RF Connections on page 37 |
| Antennas | |
| Match the module/antenna coax connections to 50 Ω —mismatched antenna impedance and cable loss negatively affect RF performance. | RF Connections on page 37 |
| If installing CDMA and UMTS modules in the same device, consider using separate antennas for maximum performance. | Antenna and Cabling on page 38 |
| Power | |
| Make sure the power supply can handle the maximum current specified for the module type. | Power Consumption on page 47 |
| Limit the total impedance of VCC and GND connections to the SIM at the connector to less than 1 Ω (including any trace impedance and lumped element components—inductors, filters, etc.). All other lines must have a trace impedance less than 2 Ω . | SIM Implementation on page 33 |
| Decouple the VCC line close to the SIM socket. The longer the trace length (impedance) from socket to module, the greater the capacitance requirement to meet compliance tests. | SIM Implementation on page 33 |
| PCB signal routing | |
| USB 2.0/3.0—Route these signals over 90 Ω differential lines on the PCB. | |
| I2C port—If supported, route these signals away from noise-sensitive signals on the PCB. | |

Table C-1: Hardware Integration Design Considerations (Continued)

| Suggestion | Section where discussed |
|--|---|
| PCM port—If supported, route these signals away from noise-sensitive signals on the PCB. | |
| EMI/ESD | |
| Investigate sources of localized interference early in the design cycle. | Methods to Mitigate Decreased Rx Performance on page 40 |
| Provide ESD protection for the SIM connector at the exposed contact point (in particular, the CLK, VCC, IO, and RESET lines). | SIM Implementation on page 33 |
| Keep very low capacitance traces on the USIM_DATA and USIM_CLK signals. | SIM Implementation on page 33 |
| To minimize noise leakage, establish a very good ground connection between the module and host. | Ground Connection on page 39 |
| Route cables away from noise sources (for example, power supplies, LCD assemblies, etc.). | Methods to Mitigate Decreased Rx Performance on page 40 |
| Shield high RF-emitting components of the host device (for example, main processor, parallel bus, etc.). | Methods to Mitigate Decreased Rx Performance on page 40 |
| Use discrete filtering on low frequency lines to filter out unwanted high-order harmonic energy. | Methods to Mitigate Decreased Rx Performance on page 40 |
| Use multi-layer PCBs to form shielding layers around high-speed clock traces. | Methods to Mitigate Decreased Rx Performance on page 40 |
| Thermal | |
| Test to worst case operating conditions—temperature, voltage, and operation mode (transmitter on 100% duty cycle, maximum power). | Thermal Considerations on page 60 |
| Use appropriate techniques to reduce module temperatures (for example, airflow, heat sinks, heat-relief tape, module placement, etc.). | Thermal Considerations on page 60 |
| Host/Modem communication | |
| Make sure the host USB driver supports remote wakeup, resume, and suspend operations, and serial port emulation. | <i>[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)</i> |
| When no valid data is being sent, do not send SOF tokens from the host (causes unnecessary power consumption). | <i>[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)</i> |

Note: All AirPrime embedded modules are factory-tested to ensure they conform to published product specifications.

Developers of OEM devices integrating Sierra Wireless AirPrime embedded modules should include a series of test phases in their manufacturing process to make sure that *their* devices work properly with the embedded modules.

Suggested phases include:

- [Acceptance Testing](#)—Testing of modules when they are received from Sierra Wireless
- [Certification Testing](#)—Testing of completed devices to obtain required certifications before beginning mass production
- [Production Testing](#)—Testing of completed devices with the modules embedded
- [Quality Assurance Testing](#)—Post-production

AT Command Entry Timing Requirement

Some AT commands require time to process before additional commands are entered. For example, the modem will return “OK” when it receives `AT!DAFTMACT`. However, if `AT!DASBAND` is received too soon after this, the modem will return an error.

When building automated test scripts, ensure that sufficient delays are embedded where necessary to avoid these errors.

Acceptance Testing

*Note: Acceptance testing is typically performed for **each** shipment received.*

When you receive a shipment from Sierra Wireless, you should make sure it is suitable before beginning production.

From a random sampling of units, test that:

- Units are operational
- Units are loaded with the correct firmware version

Acceptance Test Requirements

To perform the suggested tests, you require a test system in which to temporarily install the module, and you must be able to observe the test device's LED indicator.

Acceptance Test Procedure

The following is a suggested acceptance testing procedure using Sierra Wireless' Skylight™ software:

Note: You can perform these tests using appropriate AT commands.

Test 1: Check Power-up and Initialization

1. After installing the module, start the test system.
2. Launch Skylight.
3. Check the LED—If the LED is off, there is a problem with the module or with the connection to the LED.

Test 2: Check Version Numbers

1. From Skylight, select **Help > About**.
2. Verify that the firmware version in the **About** window is correct.
3. Close the **About** window.

If the module fails either of these tests, or is not recognized by Skylight:

1. Replace the module with one that is known to work correctly and repeat the tests.
2. If the tests are successful, reinstall the original module and repeat the tests.

If the module still does not work correctly, contact your account manager.

Certification Testing

Note: Typically, certification testing of your device with the integrated module is required one time only.

The AirPrime embedded module has been certified as described in [Regulatory Compliance and Industry Certifications on page 63](#).

When you produce a host device with a Sierra Wireless AirPrime embedded module, you must obtain certifications for the final product from appropriate regulatory bodies in the jurisdictions where it will be distributed.

The following are *some* of the regulatory bodies from which you may require certification—it is your responsibility to make sure that you obtain all necessary certifications for your product from these or other groups:

- FCC (Federal Communications Commission—www.fcc.gov)
- Industry Canada (www.ic.gc.ca)

- GCF (Global Certification Forum—www.globalcertificationforum.org) outside of North America
- PTCRB (PCS Type Certification Review Board—www.ptcrb.com) in North America

Production Testing

Note: Production testing typically continues for the life of the product.

Production testing ensures that, for each assembled device, the module is installed correctly (I/O signals are passed between the host and module), and the antenna is connected and performing to specifications (RF tests).

Typical items to test include:

- Host connectivity
- Baseband (host/module connectors)
- RF assembly (Tx and/or Rx, as appropriate)
- Network availability
- Host/device configuration issues

*Note: The amount and types of tests to perform are **your** decision—the tests listed in this section are guidelines only. Make sure that the tests you perform exercise functionality to the degree that **your** situation requires.*

Use an appropriate test station for your testing environment (see [Acceptance Test Requirements on page 78](#) for suggestions) and use AT commands to control the integrated module.

Note: Your test location must be protected from ESD to avoid interference with the module and antenna(s), assuming that your test computer is in a disassembled state. Also, consider using an RF shielding box—local government regulations may prohibit unauthorized transmissions.

Functional Production Test

This section presents a suggested procedure for performing a basic manual functional test on a laboratory bench using an AirPrime embedded module and a Mini Card Dev Kit. When you have become familiar with the testing method, use it to develop your own automated production testing procedures.

Suggested Production Tests

Consider the following tests when you design your production test procedures for devices with the AirPrime module installed.

- Visual check of the module's connectors and RF assemblies
- Module is operational

- USB connection is functional
- LED is functional
- W_DISABLE_N (enter low power mode)
- Firmware revision check
- Rx tests on main and auxiliary paths
- Tx test

Production Test Procedure

The following is a suggested test plan—you must decide which tests are appropriate for your product. You may wish to add additional tests that more fully exercise the capabilities of your product.

Using an appropriate Dev Kit-based test station, and referring to the appropriate AT command references:

1. Visually inspect the module's connectors and RF assemblies for obvious defects before installing it in the test station.
2. Ensure that the module is powered off (no voltage on VCC).
3. If using Linux, determine if any USB devices are currently connected to the computer:
 - a. Open a shell window and enter the command `ls /dev/tty/USB*`.
 - b. Record the `ttyUSBn` values that are returned; these are the currently connected USB devices. If the command returns “no such file or directory”, there are no devices currently connected.
4. Provide power to the module (voltage on VCC).
5. Test W_DISABLE_N.
6. Test USB functionality—Check for USB enumeration.
 - (Windows systems) The Device Manager shows the device under Network adapters. For example:



- (Linux systems) Enter the command `ls /dev/tty/USB*` and then record and compare the results with those from [Step 3](#). If there are any new `ttyUSBn` devices, then the modem has enumerated successfully. (The AT port is the *last* new device.)
7. Make sure your modem is connected and running, and then establish contact with the module:
 - **Windows systems:** Use a terminal emulation/communications program such as Microsoft HyperTerminal® to connect to the Sierra Wireless modem (see listings in [Step 6](#)):
 - a. Start HyperTerminal.

- b. Select **File > Connection Description**. The Connection Description dialog box appears.
 - i. Type Sierra in the Name box and click **OK**. The Connect To dialog box appears.
 - ii. Click **OK** without changing any of the displayed information. The Connect dialog box appears.
 - iii. Click **Cancel**.
 - iv. Type **ATZ** in the HyperTerminal window. If the connection is established, the message OK appears.
- **Linux systems:** Use a terminal emulation/communications program such as minicom to connect over the device handle for AT commands (see listings in [Step 6](#)):

*Note: If necessary, use **ATE1** to enable echo.*

Note: If the command “minicom” is not found, then use a different program, or download minicom and repeat this step. See [Downloading and Configuring minicom for Linux Systems on page 82](#) for details.

- i. Start minicom:
 - First use of the modem: From the command line, type minicom -s. (The ‘-s’ switch shows the configuration menu.)
 - Subsequent uses: From the command line, type minicom. (The ‘-s’ switch is assumed.)

The minicom configuration details appear and the message OK appears when the connection is established.

```

cx Telnet 00.0.00.00
Welcome to minicom 2.2
OPTIONS: I18n
Compiled on Apr 27 2007, 15:50:20.
Port /dev/ttyUSB2

Press CTRL-A Z for help on special keys
AT S7=45 S0=0 L1 U1 X4 &c1 E1 Q0
OK
CTRL-A Z for help !115200 8N1 ! NOR ! Minicom 2.2 ! UT102 ! Offline
  
```

8. Display the firmware version:
 - **AT+GMR**
9. Test the LED—Set the LED in blinking mode using this command, then visually verify that the LED turns off and on:
 - **AT!LDTEST=0,0** (LED on)
 - **AT!LDTEST=0,1** (LED off)
10. Unlock the extended AT command set (Note: Use **AT!ENTERCND?** to check command syntax, which is SKU-dependent.):
 - **AT!ENTERCN="<password>"**
11. Put the module in diagnostic/factory test mode:
 - **AT!DAFTMACT**
12. Communicate with the SIM using **+CPIN** or **+CIMI**.
When performing RF tests, use a test platform as described in [Suggested Testing Equipment on page 89](#).
13. Test RF transmission, if desired:
 - (UMTS) See [UMTS \(WCDMA\) RF Transmission Path Test on page 82](#).
 - (LTE) To test the LTE transmission path, use a call box.
14. Test RF reception, if desired:
 - (UMTS) See [UMTS \(WCDMA\) RF Receive Path Test on page 84](#).

- (LTE) See [LTE RF Receive Path Test on page 86](#).

15. Test standalone GNSS functionality—See [GNSS RF Receive Path Test on page 88](#).

Downloading and Configuring minicom for Linux Systems

Note: This procedure is for Ubuntu systems. If you are using a different Linux distribution, use the appropriate commands for your system to download minicom.

To download and configure minicom in a Ubuntu system:

Note: To install minicom, you must have root access, or be included in the sudoers list.

1. Download and install minicom—enter the following command:
`sudo apt-get install minicom`
2. When prompted, enter your user password to begin the download and installation. When minicom is installed, the shell prompt appears.
3. Configure minicom to communicate with your modem:
 - a. Start minicom with the following command:
`minicom -s`
4. Use the down-arrow key to select the **Serial port setup** option.
5. Refer to [Step 6](#) on page 80 to identify the device file handle (/dev/ttyUSBn) used for AT commands.
6. Indicate the file handle to use for AT commands—Enter A and then replace the serial device string with the AT file handle.
7. Press **Enter** twice.
8. Use the down-arrow key to select **Save setup as dfi**.
9. Select **Exit**.

UMTS (WCDMA) RF Transmission Path Test

Note: This procedure is performed in [Step 13](#) of the [Production Test Procedure on page 80](#).

The suggested test procedure that follows uses the parameters in [Table D-1](#).

Table D-1: Test Settings—UMTS Transmission Path

| | Band | Band ID | Tx Channel^a |
|----------|-------------|-----------------|-------------------------------|
| 2100 MHz | Band 1 | 9 | 9750 |
| 1900 MHz | Band 2 | 15 ^b | 9400 |
| 1800 MHz | Band 3 | 25 | 1112 |
| 1700 MHz | Band 4 | 28 | 1412 |

Table D-1: Test Settings—UMTS Transmission Path (Continued)

| | Band | Band ID | Tx Channel ^a |
|---------|--------|---------|-------------------------|
| 850 MHz | Band 5 | 22 | 4182 |
| 900 MHz | Band 8 | 29 | 2787 |

- a. Channel values shown are at the center of the corresponding bands.
- b. Either 15 (WCDMA1900A) or 16 (WCDMA1900B) may be used for testing.

To test the DUT's transmitter path:

1. Set up the power meter:



- a. Make sure the meter has been given sufficient time to warm up, if necessary, to enable it to take accurate measurements.
 - b. Zero-calibrate the meter.
 - c. Enable MAP mode.
2. Prepare the DUT using the following AT commands:
 - a. `ATIINTERCND=<password>` (Unlock extended AT command set.)
 - b. `ATIDAFTMACT` (Enter test mode.)
 - c. `ATIDASBAND=<bandValue>` (Set frequency band.)
 - See [Table D-1 on page 82](#) for appropriate <bandValue> values
 - d. `ATIDASCHAN=<channel>` (Set modem channel)
 - See [Table D-1 on page 82](#) for appropriate <channel> values
 - e. `ATIDASTXON` (Turns on the transmit path.)
 - f. `ATIDAWSTXCW=0` (Use a modulated carrier.)
`ATIDASPD=2, 75` (Set the power level. Repeat command with different offsets until desired Tx power is obtained.)
`ATIDAWSPARANGE=3` (Set to high PA gain state.)
 - g. Offset the tracking (If necessary, repeat with different offsets until the desired frequency is obtained.)
`ATIDASPD=4,35100`
 - h. Take the measurement.
 - i. `ATIDASTXOFF` (Turn off the transmitter.)

Note: This procedure describes steps using the "Power Meter: Gigatronics 8651A" (with Option 12 and Power Sensor 80701A).

3. Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal output power value.
 - Apply a tolerance of ± 5 to 6 dB to each measurement (assuming a good setup design).
 - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

Note: The module has a nominal output power of +23 dBm ± 1 dB in WCDMA mode. However, the value measured by the power meter is significantly influenced (beyond the stated ± 1 dB output power tolerance) by the test setup (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).

Note: When doing the same test over the air in an RF chamber, values are likely to be significantly lower.

UMTS (WCDMA) RF Receive Path Test

Note: This procedure is performed in [Step 14](#) of the [Production Test Procedure on page 80](#).

The suggested test procedure that follows uses the parameters in [Table D-2](#).

Table D-2: Test Settings—UMTS Receive Path

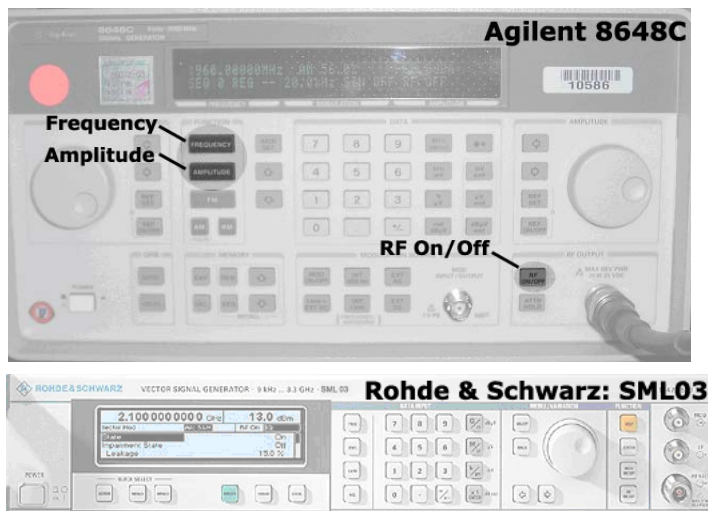
| | Band # | Frequency ^a (MHz) | Band ID | Rx Channel ^b |
|----------|--------|------------------------------|-----------------|-------------------------|
| 2100 MHz | Band 1 | 2141.20 | 9 | 9750 |
| 1900 MHz | Band 2 | 1961.20 | 15 ^c | 9400 |
| 1800 MHz | Band 3 | 1843.70 | 25 | 1112 |
| 1700 MHz | Band 4 | 2133.20 | 28 | 1412 |
| 850 MHz | Band 5 | 882.60 | 22 | 4182 |
| 900 MHz | Band 8 | 948.60 | 29 | 2787 |

- a. Receive frequencies shown are 1.2 MHz offset from center
- b. Channel values shown are at the center of the corresponding bands.
- c. Either 15 (WCDMA1900A) or 16 (WCDMA1900B) may be used for testing.

Note: This procedure describes steps using the Agilent 8648C signal generator—the Rohde & Schwarz SML03 is shown for reference only.

To test the DUT's receive path:

1. Set up the signal generator:



- a. Set the amplitude to:
 - -80 dBm
 - b. Set the frequency for the band being tested. See [Table D-2 on page 84](#) for frequency values.
2. Set up the DUT:
- a. `ATIINTERCND=<password>` (Unlock extended AT command set.)
 - b. `ATIDAFTMACT` (Put modem into factory test mode.)
 - c. `ATIDASBAND=<band>` (Set frequency band.)
 - See [Table D-2 on page 84](#) for <band> values
 - d. `ATIDASCHAN=<channel>` (Set modem channel)
 - See [Table D-2 on page 84](#) for <channel> values
 - e. `ATIDASLNAGAIN=0` (Set the LNA to maximum gain.)
 - f. `ATIDAWGAVGAGC=9400,0` (For PCS1900, channel 9400 as an example.)
The returned value is the RSSI in dBm.
3. Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal received power value.
- Apply a tolerance of ± 5 to 6 dB to each measurement (assuming a good setup design).
 - Make sure the measurement is made at a high enough level that it is not influenced by DUT-generated and ambient noise.
 - The Signal Generator power level can be adjusted and new limits found if the radiated test needs greater signal strength.
 - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

Note: The value measured from the DUT is significantly influenced by the test setup and DUT design (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).

Note: Setup of the DUT is the same as in Step 2, except for a change to AT!DAWGAVGAGC and the addition of AT!DAWSSCHAIN.

4. Test diversity paths:
 - a. Set up the signal generator as in [Step 1](#).
 - b. Set up the DUT:
 - i. AT!ENTERCND="<password>" (Unlock extended AT command set.)
 - ii. AT!DAFTMACT (Put modem into factory test mode.)
 - iii. AT!DASBAND=<band> (Set frequency band.)
 - See [Table D-2 on page 84](#) for <band> values
 - iv. AT!DAWSSCHAIN=1 (Enable the secondary chain.)
 - v. AT!DASCHAN=<channel> (Set modem channel)
 - See [Table D-2 on page 84](#) for <channel> values
 - vi. AT!DASLNAGAIN=0 (Set the LNA to maximum gain.)
 - vii. AT!DAWGAVGAGC=9400,0,1 (The '1' indicates the diversity path is used.)
 - c. Test the limits as in [Step 3](#).

LTE RF Receive Path Test

Note: This procedure is performed in Step 14 of the [Production Test Procedure on page 80](#).

The suggested test procedure that follows uses the parameters in [Table D-3](#).

Table D-3: Test Settings—LTE Receive Path

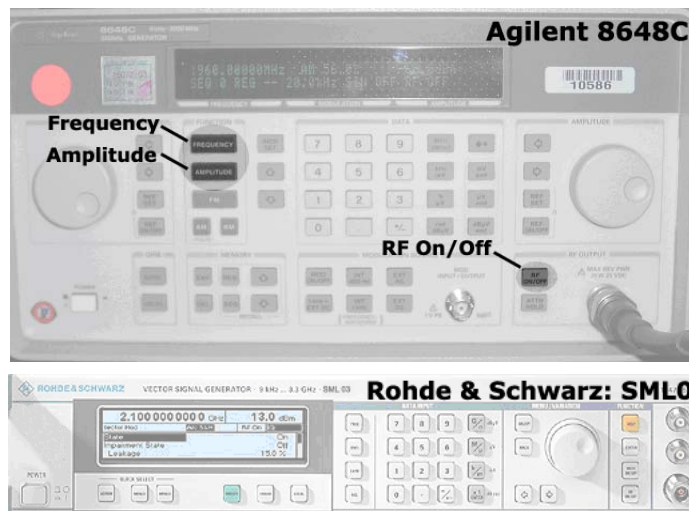
| | Band # | Frequency ^a (MHz) | Band ID | Rx Channel ^b |
|--------------------|---------|------------------------------|---------|-------------------------|
| 2100 MHz | Band 1 | 2142.00 | 34 | 18300 |
| 1900 MHz | Band 2 | 1962.00 | 43 | 18900 |
| 1800 MHz | Band 3 | 1844.50 | 44 | 19575 |
| 1700 MHz | Band 4 | 2134.50 | 42 | 20175 |
| 850 MHz | Band 5 | 883.50 | 45 | 20525 |
| 2600 MHz | Band 7 | 2657.00 | 35 | 21100 |
| 900 MHz | Band 8 | 944.50 | 47 | 21625 |
| 700 MHz | Band 12 | 739.50 | 50 | 23095 |
| 700 MHz | Band 13 | 753.00 | 36 | 23230 |
| 800 MHz | Band 20 | 808.00 | 56 | 24300 |
| 1900 MHz (G Block) | Band 25 | 1964.50 | 61 | 26365 |
| 850 MHz | Band 26 | 878.50 | 62 | 26865 |
| 2300 MHz | Band 30 | 2357.00 | 66 | 27710 |
| 2500 MHz | Band 41 | 2595.00 | 76 | 40620 |

- a. Receive frequencies shown are 2 MHz offset from center
- b. Channel values shown are at the center of the corresponding bands.

To test the DUT's receive path (or diversity path, while connected to the diversity antenna):

Note: This procedure describes steps using the Agilent 8648C signal generator—the Rohde & Schwarz SML03 is shown for reference only.

1. Set up the signal generator:



- a. Set the amplitude to -70 dBm
 - b. Set the frequency for the band being tested. See [Table D-3 on page 86](#) for frequency values.
2. Set up the DUT:
 - a. `AT+ENTERCND=<password>` (Unlock extended AT command set.)
 - b. `AT+IDAFTMACT` (Put modem into factory test mode.)
 - c. `AT+IDASBAND=<band>` (Set frequency band.)
 - See [Table D-3 on page 86](#) for <band> values
 - d. `AT+DALSTXBW=<bw>` (Set Tx bandwidth.)
 - e. `AT+DALSRXBW=<bw>` (Set Rx bandwidth.)
 - f. `AT+IDASCHAN=<channel>` (Set modem channel.)
 - See [Table D-3 on page 86](#) for <channel> values
 - g. `AT+DALGAVGAGC=<channel>,0` (Get averaged Rx AGC.)
 - See [Table D-3 on page 86](#) for <channel> values
 3. Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal received power value.
 - Apply a tolerance of ± 5 to 6 dB to each measurement (assuming a good setup design).
 - Make sure the measurement is made at a high enough level that it is not influenced by DUT-generated and ambient noise.
 - The Signal Generator power level can be adjusted and new limits found if the radiated test needs greater signal strength.
 - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

Note: The value measured from the DUT is significantly influenced by the test setup and DUT design (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).

GNSS RF Receive Path Test

The GNSS receive path uses either the dedicated GNSS connector or the shared Diversity/MIMO/GNSS connector.

To test the GNSS receive path:

1. Inject a carrier signal at -110dBm, frequency 1575.52 MHz into the GNSS Rx path at the connector. (Note that this frequency is 100 kHz higher than the actual GPS L1 center frequency.)
2. Test the signal carrier-to-noise level at the GNSS receiver:
 - a. `AT+ENTERCND=<password>` (Unlock extended AT command set.)
 - b. `AT+IDAFTMACT` (Put modem into factory test mode.)
 - c. `AT+IDACGPSTESTMODE=1` (Start CGPS diagnostic task.)
 - d. `AT+IDACGPSSTANDALONE=1` (Enter standalone RF mode.)
 - e. `AT+IDACGPSMASKON` (Enable log mask.)
 - f. `AT+IDACGPSCTON` (Return signal-to-noise and frequency measurements.)
 - g. Repeat `AT+IDACGPSCTON` five to ten times to ensure the measurements are repeatable and stable.
3. Leave the RF connection to the Mini Card device intact, and turn off the signal generator.
4. Take several more `IDACGPSCTON` readings. This will demonstrate a 'bad' signal in order to set limits for testing, if needed. This frequency offset should fall outside of the guidelines in the note below, which indicates that the CtoN result is invalid.
5. (Optional) Turn the signal generator on again, and reduce the level to -120dBm. Take more `IDACGPSCTON` readings and use these as a reference for what a marginal/poor signal would be.

Note: The response to `AT+IDACGPSCTON` for a good connection should show CtoN within 58 +/- 5dB and Freq (frequency offset) within 100000 Hz +/- 5000 Hz .

Quality Assurance Testing

Note: QA is an ongoing process based on random samples from a finished batch of devices.

The quality assurance tests that you perform on your finished products should be designed to verify the performance and quality of your devices.

The following are *some* testing suggestions that can confirm that the antenna is interfaced properly, and that the RF module is calibrated and performs to specifications:

- Module registration on cellular networks
- Power consumption

- Originate and terminate data and voice (if applicable) calls
- Cell hand-off
- Transmitter and receiver tests
- FER (Frame Error Rate) as an indicator of receiver sensitivity/performance
- Channel and average power measurements to verify that the device is transmitting within product specifications
- RF sensitivity testing—BER/BLER for different bands and modes
- Transmitter and receiver tests (based on relevant sections of the 3GPP TS51010 and 3GPP 34121 documents)

Suggested Testing Equipment

To perform production and post-production tests, you will require appropriate testing equipment. A test computer can be used to coordinate testing between the integrated module (on the development kit or host) and the measurement equipment, usually with GPIB connections. The suggested setup includes a power meter to test RF output power and a signal generator to evaluate the receiver.

Testing Assistance Provided by Sierra Wireless

Extended AT commands have been implemented to assist with performing FTA GCF tests and portions of CE Mark tests requiring radio module access. These are documented in the [2] *AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*.

Sierra Wireless offers optional professional services based assistance to [OEMs](#) with regulatory approvals.

IOT/Operator Testing

Interoperability and Operator/Carrier testing of the finished system is the responsibility of the [OEM](#). The test process will be determined with the chosen network operator(s) and will be dependent upon your business relationship with them, as well as the product's application and sales channel strategy.

Sierra Wireless offers assistance to OEMs with the testing process, if required.

Extended AT Commands for Testing

Sierra Wireless provides the [2] *AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*, which describes proprietary AT commands that may help in hardware integration design and testing (these commands are NOT intended for use by end users).

Some commands from this document that may be useful for hardware integration are listed in [Table D-4 on page 90](#).

Table D-4: Extended AT Commands

| Command | Description |
|--|---|
| Password commands | |
| !ENTERCND | Enable access to password-protected commands |
| !SETCND | Set AT command password |
| Modem reset and status commands | |
| !RESET | Reset the modem |
| !GSTATUS | Return the operation status of the modem (mode, band, channel, and so on) |
| Diagnostic commands | |
| !BAND | Select a set of frequency bands or reports current selection |
| Test commands | |
| !DAFTMACT | Put the modem into FTM (Factory Test Mode) |
| !DAFTMDEACT | Put the modem into online mode |
| !DALGAVGAGC | Return averaged Rx AGC value (LTE) |
| !DALGRXAGC | Return Rx AGC value (LTE) |
| !DALGTXAGC | Return Tx AGC value and transmitter parameters (LTE) |
| !DAOFFLINE | Place modem offline |
| !DASBAND | Set the frequency band (UMTS/GSM) |
| !DASCHAN | Set the modem channel (frequency) (UMTS/GSM) |
| !DASLNAGAIN | Set the LNA (Low Noise Amplifier) gain state |
| !DASPDM | Set the PDM (Pulse Duration Modulation) value |
| !DASTXOFF | Turn off the Tx PA (Power Amplifier) |
| !DASTXON | Turn on the Tx PA (Power Amplifier) |
| !DAWGAVGAGC | Return averaged RX AGC value (WCDMA) |
| !DAWGRIXAGC | Return the Rx AGC (Automatic Gain Control) value (UMTS) |
| !DAWINFO | Return WCDMA mode RF information |

Table D-4: Extended AT Commands

| Command | Description |
|----------------------|---|
| !DAWSCONFIGRX | Set the UMTS receiver to factory calibration settings |
| !DAWSPARANGE | Set the PA range state machine (UMTS) |
| !DAWSCHAINTCM | Place receive chain in test call mode (WCDMA) |
| !DAWSSCHAIN | Enable secondary receive chain (WCDMA) |
| !DAWSTXCW | Set the waveform used by the transmitter (UMTS) |
| !DAWSTXPWR | Set desired Tx power level (WCDMA) |

» E: Packaging

Sierra Wireless AirPrime Mini Cards are shipped in sealed boxes. The standard packaging (see [Figure 5-1](#)), contains a single tray with a capacity of 100 modules. (Note that some SKUs may have custom packaging—contact Sierra Wireless for SKU-specific details.)

In the standard packaging, Mini Cards are inserted, system connector first, into the bottom portion (T1) of a two-part tray, all facing the same direction. This allows the top edge of each Mini Card to contact the top of the triangular features in the top portion (T2) of the tray (see Detail A).

The top and bottom portions of the tray snap together at the four connection points.

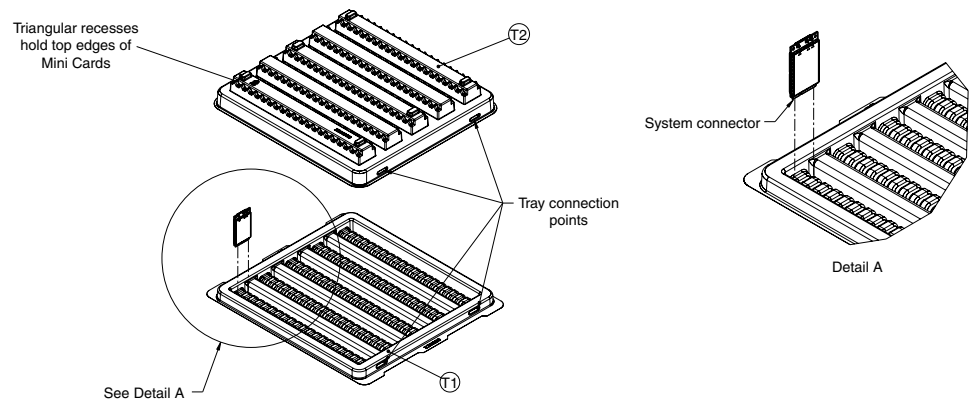


Figure 5-1: Device Placement in Module Tray

The tray is placed in a manufacturing box (T2 at the top), sealed with a security tape (P1), and a manufacturing label is placed on the bottom-right corner, above the security tape. (See [Figure 5-2](#).)

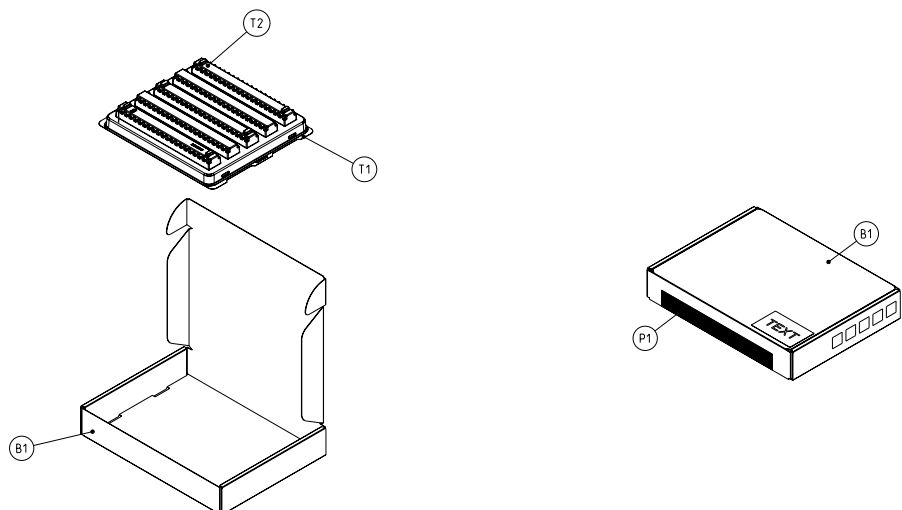


Figure 5-2: Shipping Package

»» | F: References

F

This guide deals specifically with hardware integration issues that are unique to AirPrime embedded modules.

Sierra Wireless Documents

The Sierra Wireless documents listed below are available from www.sierrawireless.com. For additional documents describing embedded module design, usage, and integration issues, contact your Sierra Wireless account representative.

Command Documents

- [1] AT Command Set for User Equipment (UE) (Release 6)
(Doc# 3GPP TS 27.007)
- [2] AirPrime EM74xx/MC74xx AT Command Reference
(Doc# 4117727)

Other Sierra Documents

- [3] PCI Express Mini Card Dev Kit Quick Start Guide
(Doc# 2130705)
- [4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)

Industry/Other Documents

The following non-Sierra Wireless references are not included in your documentation package:

- [5] FCC Regulations - Part 15 - Radio Frequency Devices
- [6] IEC-61000-4-2 level 3
- [7] IEC-61000-4-2 level (Electrostatic Discharge Immunity Test)
- [8] Mobile Station (MS) Conformance Specification; Part 4:
Subscriber Interface Module (Doc# 3GPP TS 11.10-4)
- [9] PCI Express Mini Card Electromechanical Specification Revision
2.1
- [10] Universal Serial Bus Specification, Rev 2.0
- [11] Universal Serial Bus Specification, Rev 3.0
- [12] JESD22-A114-B
- [13] JESD22-C101

»» | G: LTE CA Bandwidth Support

Note: The tables in this appendix are excerpted from 3GPP TS 36.521-1 v13.0.1.

Table G-1: LTE CA Inter-band Bandwidth Support

Note: This table is excerpted from 3GPP TS 36.521-1 v13.0.1, Table 5.4.2A.1-2.

| E-UTRA CA configuration | E-UTRA bands | 1.4 [MHz] | 3 [MHz] | 5 [MHz] | 10 [MHz] | 15 [MHz] | 20 [MHz] | Max aggregated BW [MHz] | Bandwidth combination set |
|-------------------------|--------------|-----------|---------|---------|----------|----------|----------|-------------------------|---------------------------|
| CA_1A-8A | 1 | | | Y | Y | Y | Y | 30 | 0 |
| | 8 | | | Y | Y | | | | |
| | 1 | | | Y | Y | | | 20 | 1 |
| | 8 | | | Y | Y | | | | |
| | 1 | | | Y | Y | Y | Y | 30 | 2 |
| | 8 | | Y | Y | Y | | | | |
| CA_2A-5A | 2 | | | Y | Y | Y | Y | 30 | 0 |
| | 5 | | | Y | Y | | | | |
| CA_2A-12A | 2 | | | Y | Y | Y | Y | 30 | 0 |
| | 12 | | | Y | Y | | | | |
| | 2 | | | Y | Y | Y | Y | 30 | 1 |
| | 12 | | Y | Y | Y | | | | |
| CA_2A-13A | 2 | | | Y | Y | Y | Y | 30 | 0 |
| | 13 | | | | Y | | | | |
| | 2 | | | Y | Y | | | 20 | 1 |
| | 13 | | | | Y | | | | |
| CA_2A-29A | 2 | | | Y | Y | | | 20 | 0 |
| | 29 | | Y | Y | Y | | | | |
| | 2 | | | Y | Y | | | 20 | 1 |
| | 29 | | | Y | Y | | | | |
| | 2 | | | Y | Y | Y | Y | 30 | 2 |
| | 29 | | | Y | Y | | | | |

Table G-1: LTE CA Inter-band Bandwidth Support (Continued)

Note: This table is excerpted from 3GPP TS 36.521-1 v13.0.1, Table 5.4.2A.1-2.

| E-UTRA CA configuration | E-UTRA bands | 1.4 [MHz] | 3 [MHz] | 5 [MHz] | 10 [MHz] | 15 [MHz] | 20 [MHz] | Max aggregated BW [MHz] | Bandwidth combination set |
|-------------------------|--------------|-----------|---------|---------|----------|----------|----------|-------------------------|---------------------------|
| CA_3A-7A | 3 | | | Y | Y | Y | Y | 40 | 0 |
| | 7 | | | | Y | Y | Y | | |
| CA_3A-20A | 3 | | | Y | Y | Y | Y | 30 | 0 |
| | 20 | | | Y | Y | | | | |
| | 3 | | | Y | Y | Y | Y | 40 | 1 |
| | 20 | | | Y | Y | Y | Y | | |
| CA_4A-5A | 4 | | | Y | Y | | | 20 | 0 |
| | 5 | | | Y | Y | | | | |
| | 4 | | | Y | Y | Y | Y | 30 | 1 |
| | 5 | | | Y | Y | | | | |
| CA_4A-12A | 4 | Y | Y | Y | Y | | | 20 | 0 |
| | 12 | | | Y | Y | | | | |
| | 4 | Y | Y | Y | Y | Y | Y | 30 | 1 |
| | 12 | | | Y | Y | | | | |
| | 4 | | | Y | Y | Y | Y | 30 | 2 |
| | 12 | | Y | Y | Y | | | | |
| | 4 | | | Y | Y | | | 20 | 3 |
| | 12 | | | Y | Y | | | | |
| | 4 | | | Y | Y | Y | Y | 30 | 4 |
| | 12 | | | Y | Y | | | | |
| CA_4A-13A | 4 | | | Y | Y | Y | Y | 30 | 0 |
| | 13 | | | | Y | | | | |
| | 4 | | | Y | Y | | | 20 | 1 |
| | 13 | | | | Y | | | | |

Table G-1: LTE CA Inter-band Bandwidth Support (Continued)

Note: This table is excerpted from 3GPP TS 36.521-1 v13.0.1, Table 5.4.2A.1-2.

| E-UTRA CA configuration | E-UTRA bands | 1.4 [MHz] | 3 [MHz] | 5 [MHz] | 10 [MHz] | 15 [MHz] | 20 [MHz] | Max aggregated BW [MHz] | Bandwidth combination set |
|-------------------------|--------------|-----------|---------|---------|----------|----------|----------|-------------------------|---------------------------|
| CA_4A-29A | 4 | | | Y | Y | | | 20 | 0 |
| | 29 | | Y | Y | Y | | | | |
| | 4 | | | Y | Y | | | 20 | 1 |
| | 29 | | | Y | Y | | | | |
| | 4 | | | Y | Y | Y | Y | 30 | 2 |
| | 29 | | | Y | Y | | | | |
| CA_7A-20A | 7 | | | | Y | Y | Y | 30 | 0 |
| | 20 | | | Y | Y | | | | |
| | 7 | | | | Y | Y | Y | 40 | 1 |
| | 20 | | | Y | Y | Y | Y | | |
| CA_12A-30A | 12 | | | Y | Y | | | 20 | 0 |
| | 30 | | | Y | Y | | | | |

Table G-2: LTE CA Intra-band (Contiguous) Bandwidth Support

Note: This table is excerpted from 3GPP TS 36.521-1 v13.0.1, Table 5.4.2A.1-1.

| E-UTRA CA configuration | Component carriers in order of increasing carrier frequency | | Max aggregated BW [MHz] | Bandwidth combination set |
|-------------------------|---|--------------------------------------|-------------------------|---------------------------|
| | Channel bandwidths for carrier [MHz] | Channel bandwidths for carrier [MHz] | | |
| CA_7C | 15 | 15 | 40 | 0 |
| | 20 | 20 | | |
| | 10 | 20 | 40 | 1 |
| | 15 | 15, 20 | | |
| | 20 | 10, 15, 20 | | |

Table G-2: LTE CA Intra-band (Contiguous) Bandwidth Support (Continued)

Note: This table is excerpted from 3GPP TS 36.521-1 v13.0.1, Table 5.4.2A.1-1.

| E-UTRA CA configuration | Component carriers in order of increasing carrier frequency | | Max aggregated BW [MHz] | Bandwidth combination set |
|-------------------------|---|--------------------------------------|-------------------------|---------------------------|
| | Channel bandwidths for carrier [MHz] | Channel bandwidths for carrier [MHz] | | |
| CA_41C | 10 | 20 | 40 | 0 |
| | 15 | 15, 20 | | |
| | 20 | 10, 15, 20 | | |
| | 5, 10 | 20 | 40 | 1 |
| | 15 | 15, 20 | | |
| | 20 | 5, 10, 15, 20 | | |

Table G-3: LTE CA Intra-band (Non-contiguous) Bandwidth Support

Note: This table is excerpted from 3GPP TS 36.521-1 v13.0.1, Table 5.4.2A.1-3.

| E-UTRA CA configuration | Component carriers in order of increasing carrier frequency | | Max aggregated BW [MHz] | Bandwidth combination set |
|-------------------------|---|--------------------------------------|-------------------------|---------------------------|
| | Channel bandwidths for carrier [MHz] | Channel bandwidths for carrier [MHz] | | |
| CA_2A-2A | 5, 10, 15, 20 | 5, 10, 15, 20 | 40 | 0 |
| CA_4A-4A | 5, 10, 15, 20 | 5, 10, 15, 20 | 40 | 0 |
| CA_7A-7A | 5 | 15 | 40 | 0 |
| | 10 | 10, 15 | | |
| | 15 | 15, 20 | | |
| | 20 | 20 | | |
| CA_41A-41A | 10, 15, 20 | 10, 15, 20 | 40 | 0 |
| | 5, 10, 15, 20 | 5, 10, 15, 20 | 40 | 1 |

» H: Acronyms

Table H-1: Acronyms and Definitions

| Acronym or term | Definition |
|------------------|--|
| 3GPP | 3rd Generation Partnership Project |
| 8PSK | Octagonal Phase Shift Keying |
| AGC | Automatic Gain Control |
| A-GPS | Assisted GPS |
| API | Application Programming Interface |
| BeiDou | BeiDou Navigation Satellite System A Chinese system that uses a series of satellites in geostationary and middle earth orbits to provide navigational data. |
| BER | Bit Error Rate—A measure of receive sensitivity |
| BLER | Block Error Rate |
| bluetooth | Wireless protocol for data exchange over short distances |
| CQI | Channel Quality Indication |
| COM | Communication port |
| CS | Circuit-switched |
| CSG | Closed Subscriber Group |
| CW | Continuous waveform |
| dB | Decibel = $10 \times \log_{10} (P1/P2)$ <i>P1 is calculated power; P2 is reference power</i> Decibel = $20 \times \log_{10} (V1/V2)$ <i>V1 is calculated voltage, V2 is reference voltage</i> |
| dBm | A logarithmic (base 10) measure of relative power (dB for decibels); relative to milliwatts (m). A dBm value will be 30 units (1000 times) larger (less negative) than a dBW value, because of the difference in scale (milliwatts vs. watts). |
| DC-HSPA+ | Dual Carrier HSPA+ |
| DCS | Digital Cellular System A cellular communication infrastructure that uses the 1.8 GHz radio spectrum. |
| DL | Downlink (network to mobile) |
| DRX | Discontinuous Reception |
| DSM | Distributed Shared Memory |
| DUT | Device Under Test |
| eICIC | Enhanced Inter-Cell Interference Coordination |

Table H-1: Acronyms and Definitions (Continued)

| Acronym or term | Definition |
|------------------------|--|
| EIRP | Effective (or Equivalent) Isotropic Radiated Power |
| EMC | Electromagnetic Compatibility |
| EMI | Electromagnetic Interference |
| ERP | Effective Radiated Power |
| ESD | Electrostatic Discharge |
| FCC | Federal Communications Commission The U.S. federal agency that is responsible for interstate and foreign communications. The FCC regulates commercial and private radio spectrum management, sets rates for communications services, determines standards for equipment, and controls broadcast licensing. Consult www.fcc.gov . |
| FDD | Frequency Division Duplexing |
| FDMA | Frequency Division Multiple Access |
| feICIC | Further Enhanced Inter-Cell Interference Coordination |
| FER | Frame Error Rate—A measure of receive sensitivity. |
| firmware | Software stored in ROM or EEPROM; essential programs that remain even when the system is turned off. Firmware is easier to change than hardware but more permanent than software stored on disk. |
| FOTA | Firmware Over The Air—Technology used to download firmware upgrades directly from the service provider, over the air. |
| FOV | Field Of View |
| FSN | Factory Serial Number—A unique serial number assigned to the mini card during manufacturing. |
| Galileo | A European system that uses a series of satellites in middle earth orbit to provide navigational data. |
| GCF | Global Certification Forum |
| GLONASS | Global Navigation Satellite System—A Russian system that uses a series of 24 satellites in middle circular orbit to provide navigational data. |
| GMSK | Gaussian Minimum Shift Keying modulation |
| GNSS | Global Navigation Satellite Systems (GPS, GLONASS, BeiDou, and Galileo) |
| GPS | Global Positioning System An American system that uses a series of 24 satellites in middle circular orbit to provide navigational data. |
| Host | The device into which an embedded module is integrated |
| HSDPA | High Speed Downlink Packet Access |
| HSPA+ | Enhanced HSPA, as defined in 3GPP Release 7 and beyond |
| HSUPA | High Speed Uplink Packet Access |

Table H-1: Acronyms and Definitions (Continued)

| Acronym or term | Definition |
|-----------------------|--|
| Hz | Hertz = 1 cycle/second |
| IC | Industry Canada |
| IF | Intermediate Frequency |
| IMEI | International Mobile Equipment Identity |
| IMS | IP Multimedia Subsystem—Architectural framework for delivering IP multimedia services. |
| inrush current | Peak current drawn when a device is connected or powered on |
| inter-RAT | Radio Access Technology |
| IOT | Interoperability Testing |
| IS | Interim Standard. After receiving industry consensus, the TIA forwards the standard to ANSI for approval. |
| ISIM | IMS Subscriber Identity Module (Also referred to as a SIM card) |
| LED | Light Emitting Diode. A semiconductor diode that emits visible or infrared light. |
| LHCP | Left-Hand Circular Polarized |
| LNA | Low Noise Amplifier |
| LPM | Low Power Mode |
| LPT | Line Print Terminal |
| LTE | Long Term Evolution—a high-performance air interface for cellular mobile communication systems. |
| MCS | Modulation and Coding Scheme |
| MHz | Megahertz = 10e6 Hz |
| MIMO | Multiple Input Multiple Output—wireless antenna technology that uses multiple antennas at both transmitter and receiver side. This improves performance. |
| NAS/AS | Network Access Server |
| NC | No Connect |
| NIC | Network Interface Card |
| NLIC | Non-Linear Interference Cancellation |
| NMEA | National Marine Electronics Association |
| OEM | Original Equipment Manufacturer—a company that manufactures a product and sells it to a reseller. |
| OFDMA | Orthogonal Frequency Division Multiple Access |

Table H-1: Acronyms and Definitions (Continued)

| Acronym or term | Definition |
|------------------------|--|
| OMA DM | Open Mobile Alliance Device Management—A device management protocol. |
| OTA | ‘Over the air’ (or radiated through the antenna) |
| PA | Power Amplifier |
| packet | A short, fixed-length block of data, including a header, that is transmitted as a unit in a communications network. |
| PCB | Printed Circuit Board |
| PCC | Primary Component Carrier |
| PCS | Personal Communication System A cellular communication infrastructure that uses the 1.9 GHz radio spectrum. |
| PDN | Packet Data Network |
| PMI | Pre-coding Matrix Index |
| PSS | Primary synchronisation signal |
| PST | Product Support Tools |
| PTCRB | PCS Type Certification Review Board |
| QAM | Quadrature Amplitude Modulation. This form of modulation uses amplitude, frequency, and phase to transfer data on the carrier wave. |
| QMI | Qualcomm MSM/Modem Interface |
| QOS | Quality of Service |
| QPSK | Quadrature Phase-Shift Keying |
| QPST | Qualcomm Product Support Tools |
| RAT | Radio Access Technology |
| RF | Radio Frequency |
| RI | Ring Indicator |
| roaming | A cellular subscriber is in an area where service is obtained from a cellular service provider that is not the subscriber's provider. |
| RSE | Radiated Spurious Emissions |
| RSSI | Received Signal Strength Indication |
| SCC | Secondary Component Carrier |
| SDK | Software Development Kit |
| SED | Smart Error Detection |

Table H-1: Acronyms and Definitions (Continued)

| Acronym or term | Definition |
|----------------------------|--|
| Sensitivity (Audio) | Measure of lowest power signal that the receiver can measure. |
| Sensitivity (RF) | Measure of lowest power signal at the receiver input that can provide a prescribed BER/BLER/SNR value at the receiver output. |
| SG | An LTE signaling interface for SMS (“SMS over SGs”) |
| SIB | System Information Block |
| SIM | Subscriber Identity Module. Also referred to as USIM or UICC. |
| SIMO | Single Input Multiple Output—smart antenna technology that uses a single antenna at the transmitter side and multiple antennas at the receiver side. This improves performance and security. |
| SISO | Single Input Single Output—antenna technology that uses a single antenna at both the transmitter side and the receiver side. |
| SKU | Stock Keeping Unit—identifies an inventory item: a unique code, consisting of numbers or letters and numbers, assigned to a product by a retailer for purposes of identification and inventory control. |
| SMS | Short Message Service. A feature that allows users of a wireless device on a wireless network to receive or transmit short electronic alphanumeric messages (up to 160 characters, depending on the service provider). |
| S/N | Signal-to-noise (ratio) |
| SNR | Signal-to-Noise Ratio |
| SOF | Start of Frame—A USB function. |
| SSS | Secondary synchronisation signal. |
| SUPL | Secure User Plane Location |
| TDD | Time Division Duplexing |
| TIA/EIA | Telecommunications Industry Association / Electronics Industry Association. A standards setting trade organization, whose members provide communications and information technology products, systems, distribution services and professional services in the United States and around the world. Consult www.tiaonline.org . |
| TIS | Total Isotropic Sensitivity |
| TRP | Total Radiated Power |
| UDK | Universal Development Kit (for PCI Express Mini Cards) |
| UE | User Equipment |
| UICC | Universal Integrated Circuit Card (Also referred to as a SIM card.) |
| UL | Uplink (mobile to network) |
| UMTS | Universal Mobile Telecommunications System |

Table H-1: Acronyms and Definitions (Continued)

| Acronym or term | Definition |
|-----------------|---|
| USB | Universal Serial Bus |
| USIM | Universal Subscriber Identity Module (UMTS) |
| VCC | Supply voltage |
| VSWR | Voltage Standing Wave Ratio |
| WAN | Wide Area Network |
| WCDMA | Wideband Code Division Multiple Access (also referred to as UMTS) |
| WLAN | Wireless Local Area Network |
| ZIF | Zero Intermediate Frequency |
| ZUC | ZUC stream cypher |

Index

Numerics

- 3D gain, average gain
 - 3D average (GNSS), 74
- 3GPP compliance
 - LTE, 21
 - UMTS, 21

A

- acceptance tests, 77
- accessories, 19
- accuracy (GNSS), 46
- acquisition time (GNSS), 46
- acronyms and definitions, 101–106
- A-GNSS, 18
- A-GPS, 18
- antenna
 - connection considerations, 37
 - connectors, 23
 - custom, design, 38
 - diversity antenna, disabling, 38
 - GNSS, specifications, recommended, 73
 - limit, matching coaxial connections, 37
 - location, considerations, 38
 - matching, considerations, 38
 - maximum cable loss, 37
 - routing, 38
 - specification, 67–77, 71–74
 - specifications, recommended, 71
 - testing, 74
- antennas
 - design checklist, 75
- API, 55
- application interface features, 16
- approvals, regulatory and industry, 63
- AT commands, 90
- averaged call mode DC power consumption, 48
- averaged standby DC power consumption, 47

B

- bands supported, RF
 - summary, 15
 - LTE, 42, 43, 82, 84, 86
- bearers, dedicated, 18
- BER (Bit Error Rate), 41
- bit error rate (BER)
 - measure of sensitivity, 41
- block diagram
 - expanded RF, 25
 - system, 24
- bottom view, 58

C

- cable loss
 - antenna, maximum, 37
- capacitors
 - with SIM, 33
 - with XIM_DATA / XIM_CLK, 33
- carrier/operator testing, 89
- cell selection, 17
- certification tests, 78
- checklist, design, 75
- communications, host to modem
 - design checklist, 76
- conducted Tx power tolerances, 45
- connection
 - grounding, 39
- connectors, 37
- connectors, required
 - host-module, 19
- control interface, 34
- CQI, 18

D

- DC power consumption
 - averaged call mode, 48
 - averaged standby, 47
- desense. See RF
- design checklist
 - antennas, 75
 - component placement, 75
 - EMI/ESD, 76
 - host/modem communications, 76
 - power, 75
 - thermal, 76
 - USB3, 75
- detach procedure, 18
- Development Kit contents, 19
- digital interface, 36
- dimensioned view, 58
- dimensions, 57, 58
- diversity antenna
 - disabling, 38
- diversity connector, location, 37
- drop specifications, 57

E

- EDGE
 - connector, required, 19
- electrical specifications, 23
- electrostatic discharge specifications, 57
- electrostatic discharge. See ESD
- envelope correlation coefficient, 72

environmental specifications, [57–59](#)

ESD

- design checklist, [76](#)
- protection requirements, [59](#)

ESD specifications, [57](#)

expanded RF block diagram, [25](#)

F

field of view, [73](#)

filtering, RF desense, [40](#)

form factor, [57](#)

FOV, [73](#)

free space average gain, [74](#)

frequencies supported, [41](#)

frequency band support
LTE, [42](#), [43](#), [82](#), [84](#), [86](#)

G

gain

- GNSS, [74](#)
- maximum, [64](#), [72](#)
- mean effective, [72](#)
- mean effective imbalance, [72](#)

GNSS

- antenna specifications, recommended, [73](#)
- connector location, [37](#)
- features supported, [18](#)
- specifications, [45](#)

ground specifications, [30](#)

grounding

- connection considerations, [39](#)

H

host interface

- pin assignments, [25](#)

humidity specifications, [57](#)

I

I/O connector location, [37](#)

I/O rise time requirements, [33](#)

impedance

- module–antenna, [38](#)
- SIM, [33](#)

industry approvals, [63](#)

integration requirements, [19](#)

interface

- control interface, [34](#)
- digital interface, [36](#)
- feature summary, [16](#)
- host, pin assignments, [25](#)
- QMI, [55](#)
- SIM, [31](#)
- software, [55](#)
- USB, [30](#)

interference

- device generated, [40](#)
- host-generated, [39](#)
- power supply noise, [52](#)
- wireless devices, [39](#)

Interoperability testing, [89](#)

intra-LTE mobility, [18](#)

IOT testing, [89](#)

iRAT, [18](#)

isolation, [73](#), [74](#)

L

labeling, [59](#)

LED

- example, [35](#)

LED output, [23](#), [34](#), [35](#)

LTE

- 3GPP compliance, [21](#)
- bandwidth support, [42](#)
- bandwidth support, LTE CA, [97](#)
- features, [17](#)
- frequency band support, [42](#), [43](#), [82](#), [84](#), [86](#)

M

mean effective gain, [72](#)

mean effective gain imbalance, [72](#)

mechanical specifications, [57–59](#)

MIB, [17](#)

minicom

- downloading and installing, [82](#)

module

- power states, [49–50](#)

N

NAS/AS security, [17](#)

noise

- leakage, minimizing, [39](#)
- RF interference, power supply, [52](#)

O

OEM

- assistance with testing, [89](#)
- labeling, [59](#)

operator/carrier testing, [89](#)

ordering information, 19

P

packaging, 93

paging procedures, 18

PCB

multi-layer, shielding for RF desense, 40

PDN connections, multiple, 18

pin assignments, host interface, 25

PMI, 18

polarization, 74

position location, 18

power

design checklist, 75

handling, 73

power-up timing, 51

ramp-up timing, 51

state machines, 50

states, module, 49–50

supply, RF interference, 52

supply, ripple limit, 52

power consumption, DC

averaged call mode, 48

averaged standby, 47

power specifications, 30

power tolerances, conducted Tx, 45

Product Support Tool, QUALCOMM (QPST), 55

production tests, 79

PSS, 17

Q

QMI interface, 55

QPST (QUALCOMM Product Support Tool), 55

QUALCOMM Product Support Tool (QPST), 55

quality assurance tests, 88

QXDM support, 55

R

radiated efficiency, total, 72

radiated sensitivity measurement, 40

radiated spurious emissions, 40

radiation patterns, 72

references, 95

regulatory approvals, 63

regulatory information, 63–66

FCC, 64

limitation of liability, 63

safety and hazards, 64

reset device, 36

resistors, external pull-up, 33

RF

antenna cable loss, maximum, 37

antenna connection, considerations, 37

connectors, required, 19

desense

device-generated, 39

harmonic energy, filtering, 40

mitigation suggestions, 40

shielding suggestions, 40

interference

other devices, 40

power supply, 52

wireless devices, 39

RF bands supported

summary, 15

LTE, 42, 43, 82, 84, 86

RF block diagram, expanded, 25

RF connector location, 37

RF specifications, 37–46

RI, 18

RSE, 40

Rx sensitivity

conducted, 44, 45

S

sales

ordering, 19

SDKs available, 55

SED

see Smart Error Detection

See also W_DISABLE_N, 35

sensitivity

conducted, RF parameter, 44, 45

defined, 41

radiated measurement, overview, 40

testing, overview, 41

shielding

module, compliance, 37

reducing RF desense, 40

shock specifications, 57

SIB, 17

signals, 34

SYSTEM_RESET_N, 36

W_DISABLE_N, 35

WAKE_N, 34

WLAN_LED_N, 35

SIM

capacitor recommendations, 33

card contacts, 32

clock rate, 33

connector, required, 19

electrical specifications, 33

impedance, connectors, 33

interface, 31

interface diagram, 32

operation, 33

Smart Error Detection

detecting module reset, 52

- SMS features, [18](#)
- Snow 3G/AES security, [17](#)
- software interface, [55](#)
- specifications
 - electrical, [23](#)
 - environmental specifications, [57–59](#)
 - GNSS, [45](#)
 - mechanical, [57–59](#)
 - RF, [37–46](#)
- SSS, [17](#)
- standalone mode, concurrent, GNSS, [18](#)
- standalone mode, GPS/GLONASS, [18](#)
- standby DC power consumption, averaged, [47](#)
- state machines, [50](#)
- support
 - testing assistance by Sierra Wireless, [89](#)
 - tools, [55](#)
- system acquisition, [17](#)
- system block diagram, [24](#)
- SYSTEM_RESET_N, [36](#)

T

- temperature specifications, [57](#)
- temperature, module. See thermal
- testing
 - overview, [77](#)
 - acceptance tests, [77](#)
 - assistance provided by Sierra Wireless, [89](#)
 - certification tests, [78](#)
 - equipment, suggested, [89](#)
 - interoperability and operator/carrier testing, [89](#)
 - manual functional test, suggested, [79](#)
 - production tests, [79](#)
 - quality assurance tests, [88](#)
 - RF receive path, LTE, [86](#)
 - suggestions, [77–91](#)
- thermal
 - considerations, [60–62](#)
 - design checklist, [76](#)
 - dissipation, factors affecting, [60](#)
 - dissipation, suggestions, [60](#)
 - internal temperature, maximum, [62](#)
 - testing, module, [61–62](#)

- timing
 - power ramp-up, [51](#)
 - power-up, [51](#)
- top view, [58](#)
- tracking session
 - automatic, [18](#)
 - standalone, [18](#)
- Tx power tolerances, conducted, [45](#)

U

- UDK, [19](#)
- UMTS
 - 3GPP compliance, [21](#)
- Universal Development Kit, [19](#)
- USB
 - drivers, user-developed, [31](#)
 - high / full speed throughput performance, [31](#)
 - interface, [30](#)
- USB3
 - design checklist, [75](#)

V

- vibration specifications, [57](#)
- VSWR, [71, 74](#)

W

- W_DISABLE_N, [34, 35](#)
- WAKE_N, [23, 34](#)
- Wireless Disable, [23](#)
- Wireless Disable (Main RF), [35](#)
- WLAN_LED_N, [34, 35](#)

Z

- ZIF (Zero Intermediate Frequency), [39](#)